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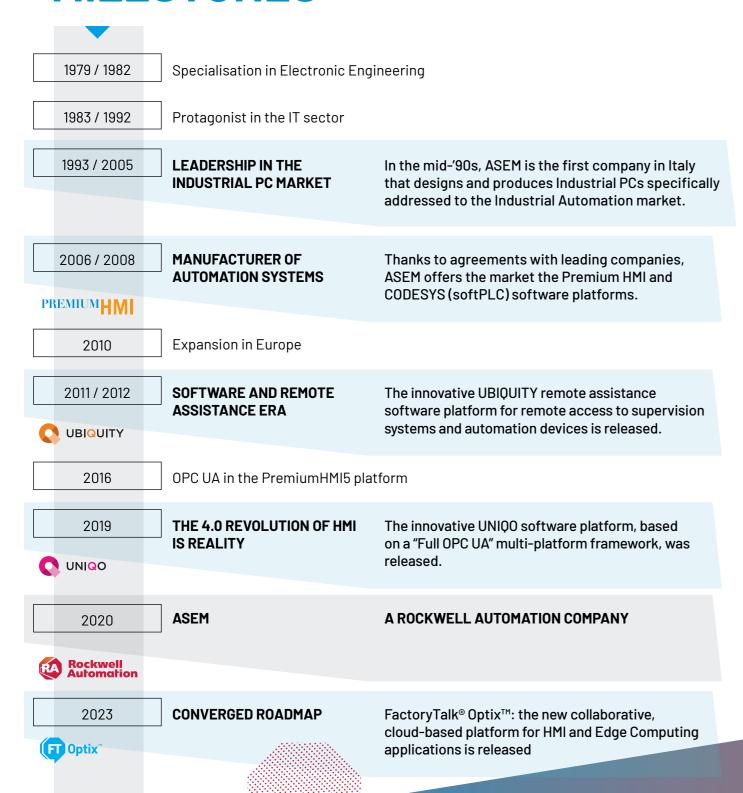


30%

dedicated to R&D



MILESTONES



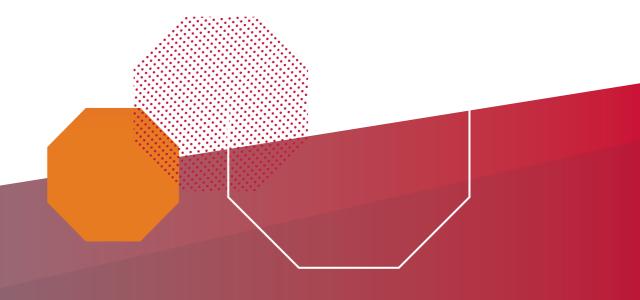




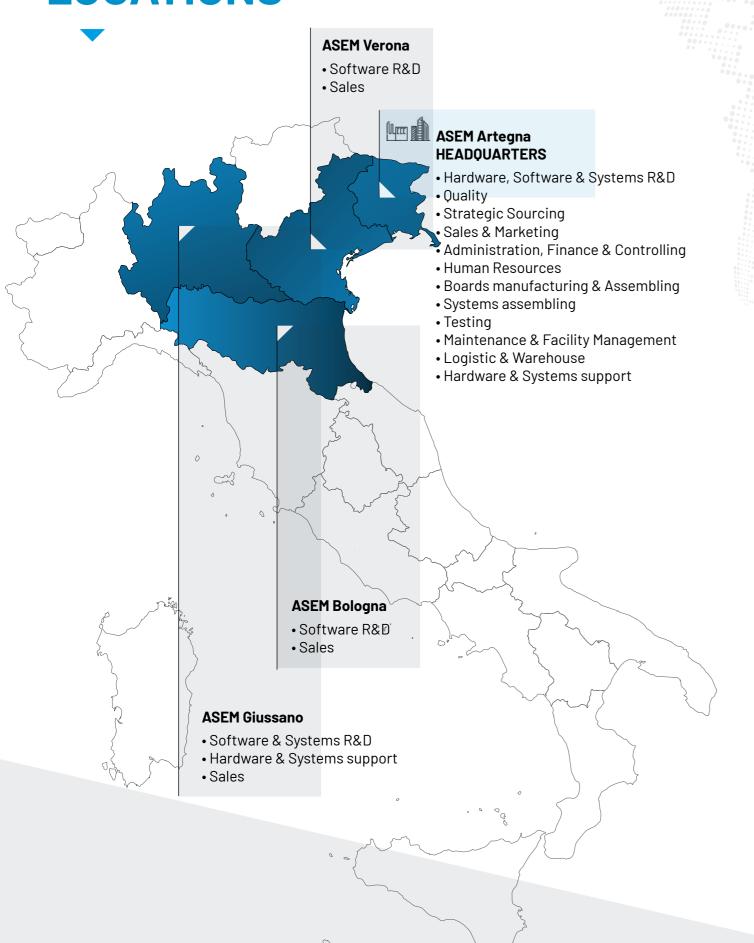


In 2020, ASEM joined the Rockwell Automation Group, the world's largest company dedicated to industrial automation and manufacturing information management, headquartered in Milwaukee (USA) and with a major presence in the EMEA, Asia Pacific and Latin America regions.

This allowed ASEM to grow in a global context and become the centre of excellence of the group for hardware, visualisation and integrated systems with application software.



LOCATIONS





TECHNOLOGIES IS KEY TO SUCCESS

THE SEAMLESS II 30% delle risorse umane di ASEM è impegnato in attività di Ricerca e Sviluppo. Il team comprende **INTEGRATION** ingegneri altamente specializzati con competenze complementari che comprendono tutte le esigenze OF HARDWARE di progettazione elettronica e meccanica nonché quelle di sviluppo firmware e software. Dalla AND SOFTWARE stretta collaborazione con i principali trendsetter tecnologici e dal confronto continuo con i clienti nascono le specifiche dell'architettura hardware, firmware, sistemistica e software di ogni singolo

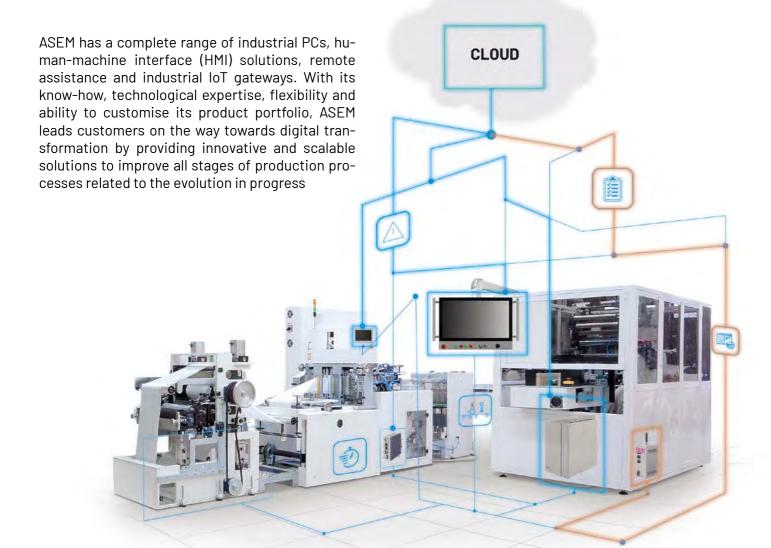


ANECHOIC CHAMBER

ASEM has made a major investment in product certification: the installation of a full compliant anechoic chamber.

The anechoic chamber allows for increased control throughout the design phase: any corrections and adjustments on prototypes can be carried out in extremely reduced time, eliminating shipping and logistics time with external entities.

MAXIMUM SYSTEM CONFIGURABILITY AND FLEXIBILITY



MECHANICAL DESIGN

- 3D modelling and simulation of mechanical assembly and coupling
- Analysis and thermal simulations for dissipation dimensioning
- Integration of mechanical and electronic CAD for more efficient and precise design

ELECTRONIC DESIGN

- Designing motherboards based on Intel® x86 and ARM NXP platforms
- Creation of PCB masters
- Verification of signal integrity through CAD simulation
- In-house laboratory for EMC compatibility testing



OPERATING SYSTEMS & FIRMWARE DEVELOPMENT

- Development, testing and customisation of operating systems for IPCs
- Development, testing and customisation of operating systems for ARM platforms
- Development and testing of drivers for x86 platforms
- Development and testing of BIOS for x86 platforms
- · Configuration and testing of systems for real-time applications

SOFTWARE DEVELOPMENT WITH **AGILE METHODOLOGY**

- DevOps
- Extreme Programming (XP)
- Lean Software Development





FLEXIBILITY AND INNOVATION

ASEM offers a complete range of reliable, robust, highly configurable and expandable te assistance and can optionally integrate UNIQO industrial PCs and monitors, with a panel, arm, wall or DIN-rail mounting arrangement to meet diverse market requirements.

All IPCs integrate UBIQUITY software for remosoftware to set up modern HMIs, IIoT gateways and Industry 4.0 applications or CODESYS software that transforms ASEM systems into powerful controllers.









SCALABLE PERFORMANCE, EXPANDABILITY **AND CONFIGURATION**

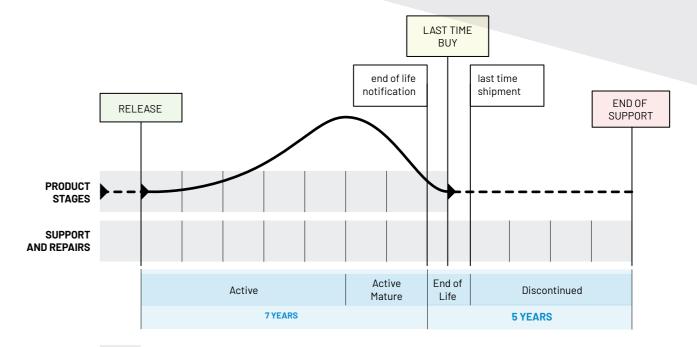
The market demands high-performance systems, more computational power, better graphics, integrated IIoT functionality and reduced power consumption. The ASEM IPCs use Intel® processors, ranging from low-power Atoms for entrylevel applications, up to the highest performance eleventhgeneration Intel® CoreTM processors for higher performance, next-generation graphics and integrated connectivity. The motherboards of the systems allow various levels of expandability in terms of communication interfaces and expansion slots and minimise internal wiring and connections to make the systems more reliable and resistant even to the potential vibrations typical of industrial environments.

CONNECTIVITY AND COMMUNICATION

To respond to multiple industrial applications, the need for communication between industrial networks and computer networks, and the most recent needs arising from the Industry 4.0 revolution, with increasingly connected and automated smart factories requiring advanced connections between MES systems, ERPs and production machines, ASEM offers systems equipped with wireless connectivity using combined Wi-Fi 5 and Bluetooth modules and 4G Global modems in addition to traditional connectivity through wired networks. Furthermore, TSN technology is integrated into the systems to ensure ultrareliable low-latency machine-to-machine communications at Gigabit speeds, significantly contributing to improving the performance and efficiency of real-time processes. Optionally, UNIQO, the Full OPC UA cross-platform software platform, can be integrated into the systems for the developing HMI applications, IIoT and Industry 4.0 solutions capable of communicating with any automation device.



The superior design and production processes combined with close collaboration with technological trendsetters allow ASEM to guarantee a life cycle of at least 7 years for systems and repairability, with the availability of spare parts, for at least a further 5 years. End of Life, Last Time Buy and Last Time Shipment procedures are in place 6 months before the end of each product's life cycle.





Active Most current offering within a product category.

Active Mature Product is fully supported, but a newer product or family exists. Gain value by migrating.

End of Life Discontinued date announced - actively execute migrations and last time buys. Product generally orderable until the

Discontinued New product no longer manufactured or procured. Repair/exchange services will be available for a limited period of time.

DESIGN, ERGONOMICS AND RELIABILITY

The complete control of all stages of the production process, and over 40 years of experience in mechanical design and industrialisation allow ASEM to produce IPCs and industrial monitors with Italian-style design, with attention to every detail, and high reliability and durability. Chassis are generally made of galvanised steel, aluminium or stainless steel and are the result of industrialisation based on perfect integration between electronic boards and mechanical components and accurate thermodynamic and fluid-dynamic analyses.

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SYSTEM TRACEABILITY

The ASEM systems integrate "ASEM System Identity", a non-volatile memory that contains system identification data in addition to customer data useful for system traceability.

OPERATING SYSTEMS

Operating systems are continuously updated and ASEM ensures full compatibility of x86 systems with Windows operating systems and Linux distributions. The ASEM Team also supports the implementation of customer-made images and develops customised images to be applied to its systems.







All ASEM panel-mounted systems are designed to meet any requirements aesthetic, ergonomic and robustness requirements and guarantee a degree of protection up to IP69K, making them the ideal solution for any application industrial.

LCDs are available with backlighted displays LED in 4:3, 5:4 and Wide aspect ratios, from 4.3" to 24", with resolutions up to Full HD.

The single CUT-OUT allows perfect interchangeability between IPC panel families, monitors and operator panels. Front panels with QT CUT-OUT differ from front panels with HT and A/B CUTOUT because of the minimized frame, which has more modern design and sophisticated design.





ALUMINUM FRONT PANEL (ALU) AND RESISTIVE TOUCHSCREEN

Front panels made of anodized aluminum with protection rating IP65, against dust and water jets. These panels integrate a resistive 5-wire touchscreen, which provides high shock resistance and the ability to make pressure on the screen not only with the fingers, also with other objects such as a stylus, achieving a very high degree of precision. Panels having HT CUT-OUT provide a front-accessible USB interface.



TRUE FLAT ALUMINIUM FRONT PANELS (TF) AND RESISTIVE TOUCHSCREEN

True Flat technology ensures a totally flat surface, without recesses, completely insulated from external agents and allows a greater ease of panel cleaning. This technology allows the seamless integration between touchscreen and bezel, making the front panel more pleasing to the touch and to the eye. These panels are made with a special manufacturing process within a clean room to avoid environmental contamination such as dust present in the air. The panels are completely sealed against the dust itself and protected against water jets thanks to the IP65 degree of protection and integrate a 5-wire resistive touchscreen. Just as the ALU panels, the TF panels having HT CUT-OUT provide a USB interface accessible frontally.



TRUE FLAT ALUMINIUM FRONT PANELS (TFM) WITH GLASS PROJECTED CAPACITIVE MULTITOUCH SCREEN

Wide format front panels with solid aluminum frame, surface of tempered glass with True Flat technology that gives maximum resistance to environmental conditions and facilitates cleaning. These panels integrate a multitouch projected capacitive touchscreen. The layer glass surface gives the screen greater brilliance and sharpness of images, greater scratch resistance and less of wear and tear. The user experience is more pleasant than with the touchscreen resistive due to the high touch sensitivity. The capacitive touchscreen allows you to interact with various elements on the screen through gestures typical of the mobile world, such as zoom, swipe, and rotate with high touch sensitivity and high level of precision. The touchscreen capacitive supports up to 10 simultaneous touches.



STAINLESS STEEL FRONT PANELS (TFK)AND RESISTIVE TOUCHSCREEN

Stainless steel front panels with an IP66K (TFX) and IP69K (TFK and TFMK), particularly suitable for the pharmaceutical and Food&Beverage market, where maximum protection is required against high pressure washing and against dust penetration. They are equipped with hygienic silicone seals, and the durable front film is specially designed to support numerous washing cycles.



The panels TFK and TFMK front panels are available in Wide aspect ratio while TFX front panels are available in 4:3 and 5:4 aspect ratios.

The TFX and TFK front panels include a resistive touchscreen while the TFMK panels integrate a multitouch projected capacitive touchscreen.

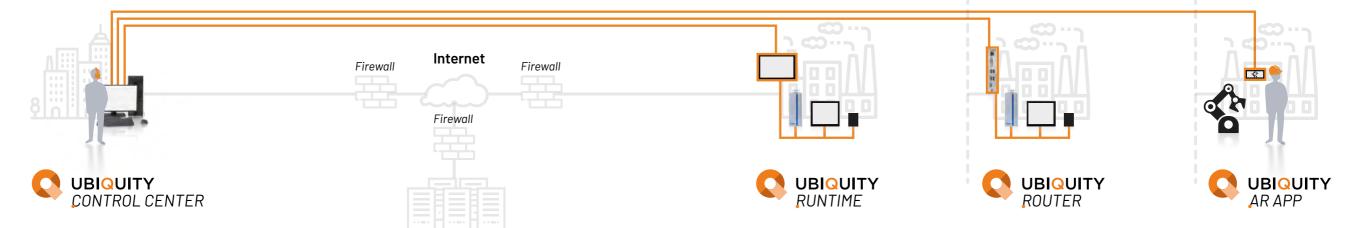




INTEGRATED REMOTE ASSISTANCE IN ALL IPCS

Comprehensive, secure and certified technology for remote assistance using interactive services and optimised VPN connection for access to the automation subnetwork.





UBIQUITY Server Infrastructure



Available both as a software solution for WinCE, Win32/64 and Linux systems and as an all-in-one router solution, also with a 4G Global Wi-Fi Modem and 4-port Ethernet switch. Installation does not require IT skills to configure the networks and various firewalls, the use of which is facilitated by a user-friendly interface that allows access to remote systems (PLCs, inverters, drives, etc.) with a simple click using a VPN optimised for industrial communications.

The solution allows the transparent management of remote systems as if they were connected to the customer's corporate network, bypassing the network administrator's intervention on any NATs, proxies, firewalls, public IPs or reserved ports, with the advantage of having all the company's expertise available to solve any arising problems, eliminating distances and the need for on-site travel and drastically slashing after-sales assistance costs. UBIQUITY is also particularly useful in the installation and commissioning phases of machinery to make changes and updates to application software and for the remote debugging of PLCs or other automation devices.

In recent years, ASEM has expanded the offerings of the UBIQUITY remote service platform by offering a set of closely related innovative services, called UBIQUITY X. Cloud-based and seamlessly integrated into the infrastructure, they help automated machine builders and industrial system integrators meet the emerging demands of manufacturing companies committed to transforming traditional factories into digital Smart Factories. The main service of UBIQUITY X is the possibility of assisting with the aid of augmented reality through the new "UBIQUITY AR" (Augmented Reality) application, available for iOS and Android devices, which amplifies the experience of both the operators of the automatic machines and the service technicians during remote assistance.

UBIQUITY has long since been certified as compliant with IEC 62443, which covers the IT security of industrial communications using the Internet as a transport medium, and also includes a two-factor authentication mode using standard apps for iOS and Android



VISUALIZATION FOR VISIONARIES

The new collaborative, cloud-based platform for HMI and Edge Computing applications, changing the world of visualization in the era of digital transformation



CLOUD-BASED EDITOR AND COLLABORATIVE **DEVELOPMENT**

The new SaaS (Software-as-a-Service) model, which parallels the classic on-premise model, allows the development environment to be used directly from a browser at any time and from anywhere, lowering management costs and ensuring that the most up-to-date version available and even all previous versions are always used without the need for multiple local installations. Not only that, by leveraging a distributed version control system such as GitHub, developers can collaborate individually and in parallel, saving their own changes in the cloud and later sharing and merging them with others. The system automatically keeps track of who, what, and when the changes were made, allowing easy management of any conflict, all without the need for centralized private server support.



DISCOVER SOLUTIONS AND FEATURES OF

It is the innovative software platform perfect to design modern, responsive HMIs with a high-level user experience, IIoT Gateways, Edge Computing applications and in general solutions related to Industry 4.0 needs.

Thanks to the fully modular and extremely flexible architecture developed with cross-platform technologies, FT Optix™ enables the creation of applications compatible with ARM and x86 platforms with Windows and Linux operating systems, providing maximum flexibility to designers, who can choose the platform that best suits the application.

FT Optix™ is part of the cloud-based FactoryTalk® Design Hub™ suite, which allows the design team to collaborate on HMI application development through a distributed version control system, simplifying software management, increasing productivity and accelerating time to market.



THE LICENSE AS A **CONTAINER OF TOKENS**

Each FT Optix™ Runtime license corresponds to a "token container" within which the designer can select and activate the functions necessary for application development. Each function has a token value associated with it, and some functions can be used for free without having a token cost. The selection of components and functions to be activated and used in the project is done at the time of programming with FT Optix™ Studio.

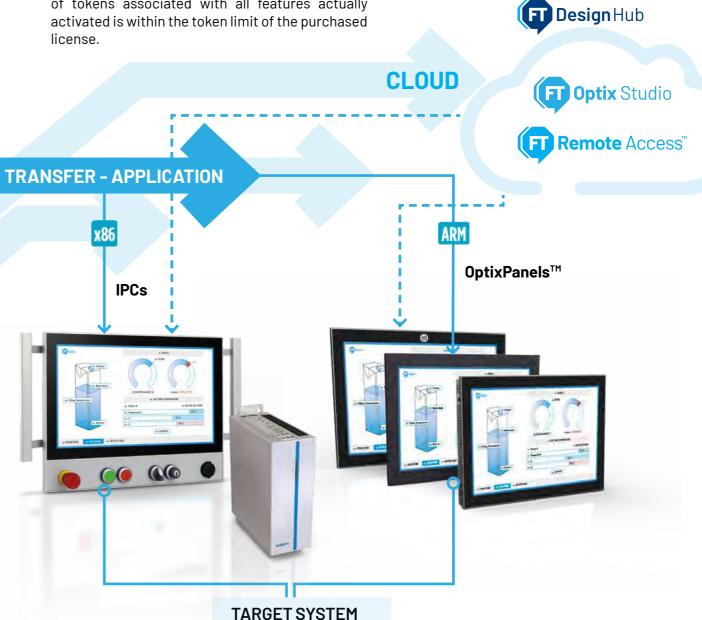
FT Optix™ Runtime verifies that the total amount of tokens associated with all features actually license.



CROSS-PLATFORM SUPPORT

FT Optix™ Runtime licenses are available:

- for both Windows and Linux operating systems
- for x86 ASEM VK/ HT/QT/BM/PB platforms, ASEM 6300 and third-party systems
- for ARM platforms on OptixPanel™ embedded systems



PREMIUM | M

SCALABLE, OPEN AND FLEXIBLE OPERATOR INTERFACES

With the Premium HMI software platform, ASEM has been marketing visualisation systems for some time now. The solutions are highly appreciated for the quantity and quality of the functions available and for the transversal nature of the platform allowing any one project to be used indifferently on HMI solutions based on ARM or x86 hardware platforms and with Runtime for WinCE or Win 32/64 operating systems without any need to modify or change settings in the "Premium HMI Studio" development tool. Several releases of this tried and tested platform have been released over the years. Since the 5.1 Premium version, HMI supports OPC UA Server functions for both Windows 32/64 and Windows CE systems. Premium HMI 5.1 is the optimal solution for the realisation of interoperable applications compatible with Industry 4.0 standards. A Premium HMI project can be conveniently configured to acquire field data through PLC communication protocols and the OPC UA client and then share it, through the OPC UA Server, with other systems or machines, to achieve optimal integration in the most heterogeneous scenarios. Premium HMI 5.1 supports the use of Active Directory services to authenticate HMI project users through direct interfacing with Domain Controllers, by simplifying the implementation of CFR 21 Part 11 compliant applications.



With the user-friendly object-oriented design, project debugging tools and the possibility of using a single development environment for any type of application (from the simplest on operator panels to the most complex on IPC panels or the most innovative on intelligent mobile devices), the Premium HMI it is easy to achieve significant time savings in learning, personnel training, maintenance, support and end-user service.

Premium HMI Mobile is the ASEM app that offers the possibility to view and interact with Premium HMI projects running on the operator terminal of the industrial machine also from iOS and Android devices connected through Wi-Fi local area network to the factory network, offering mobile and multitouch support to project management.



OF PLC AND MOTION LOGIC IN A SINGLE DEVELOPMENT TOOL

CODESYS is a global standard in industrial automation and the world's number one SoftPLC platform, independent of multinational PLC manufacturers. Integrated into ASEM IPCs, it transforms systems into powerful IEC 61131-3 controllers with a highly efficient implementation of the 3.5 version that quarantees deterministic execution of PLC control logic with Win 32/64 and Linux operating systems and full portability of projects between different operating systems and hardware platforms with no need for intervening on the project code. The CODESYS platform, like all traditional PLCs, provides a development environment (CODESYS Engineering) for making projects, which are then executed by the runtime, and the availability of the most popular industrial fieldbuses in master mode (such tion with field peripherals.

To ensure data flow traceability and information historisation, the ASEM IPCs optionally include a UPS power supply with integrated electronics and an external battery and 512Kb of MRAM (Magnetoresistive RAM) for storing retentive variables.



PORTFOLIO OVERVIEW





PANEL IPCS

P. 34-54

IPC Panels are low-power, high-performance systems, available with a wide choice of TFT LCDs from 7" to 24" and various types of front panels. The wide range of IPCs can meet all performance, configurability and expandability requirements in the industrial environment.

QT2150 & HT2150	p.34	QT2200 & HT2200	p.36	QT2250 & HT2250	p.40
QT3400/3600 & HT3400/3600	p.42	QT3500 & HT3500	p.46	QT5400/5600 & HT5400/5600	p.50



BOX IPCS

P. 58-78

IPC boxes are systems for wall-mounted and book-mounted installations, which meet all performance and installation space requirements. They offer extensive expandability with a large number of accessories and interface expansion cards.

PB2150 & BM2150	p.58	PB2200 & BM2200	p.60	PB2250 & BM2250 p.62
BM3300	p.64	PB3400/3600 & BM3400/3600	p.66	PB3500 & BM3500 p.70
BM3800	p.74	PB5400/5600	p.78	



ULTRA-COMPACT IPCS

P. 86-90

Ultra-compact IPCs are extremely ergonomic, robust systems that are ideal for applications in small spaces where high processing capacity is required.

The product range provides a wide configurability to meet the needs required in many IIoT scenarios.

BM1XY FAMILY

PRODUCT RATINGS

All products were evaluated according to three parameters:



PERFORMANCE



EXPANDABILITY



CONFIGURABILITY



ARM/VESA MOUNTING IPCS

P. 94

The arm mounting IPCs are fanless, compact, elegant systems that offer excellent performance and can be used in various industrial applications due to their high configurability. They are available with a customisable control area and various accessories that improve ergonomics, providing a wide range of customisation possibilities.

SERIE VK3500

RACK MOUNTING IPCS

P. 98

The rack mounting IPC 19" 4U devices offer high computing capacity and high reliability using heavy-duty motherboards for 24/7 industrial applications. They are available in long and short versions.

PR4XXX

p.98



INDUSTRIAL MONITORS

P. 104-110

Industrial monitors have the same robust, reliable and aesthetic characteristics as IPC panels. They are available with different installation modes, with the possibility for some systems to integrate a configurable control area and various accessories. All monitors integrate RVL technology for remote DVI-D and USB 2.0 signals up to 100m.

MQ200 & MH200 p.104

SFRIF MK200

MX200

p.108



QT2150 & HT2150



- TFT LCDs in 8.4", 10.4", 12.1", 15" in 4:3 aspect ratio and 7", 10.1", 12.1", 15.6" in Wide aspect ratio
- Aluminum (ALU) and aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Intel® Celeron® processors of Bay Trail SoC generation
- RAM up to 8GB
- Built-in UPS with external battery pack (optional)
- Available in SL version with reduced depth and SO version with the possibility to install additional interfaces

DOWNLOAD THE PRODUCT SHEET











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		QT2150-ALU	QT2150-TFM	HT2150-ALU	HT2150-TF			
LED BACKLIGHT TFT	LCD	10.1″ W - 12.1″ W -	00x480 1280x800 1280x800 1366x768	8.4" - 8 10.1" W - 10.4" - 4 12.1" - 8 12.1" - 1 15" - 10	00x480 00x600 1280x800 800x600 00x600 024x768 1280x800 24x768 1366x768			
CUT-OUT		Q)T	ŀ	İT			
FRONT USB			-	1x USB 2.0 (Тур	e-A), protected			
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch	Resistiv	e 5 wires			
FRONT PANEL	Material	Aluminum	True Flat Aluminum	Aluminum	True Flat Aluminum			
	ASEM Logo		_	Adhesive label	Silk screen printed			
PROTECTION GRADE	IP rating		IP65	- frontal				
PROTECTION GRADE	NEMA rating	UL Type 1, 4x	(indoor only)	UL Type 1, 4x (in	door only) and 12			
CACE	Installation		Panel	mounting				
CASE	Material		Zinc-coated	skin pass steel				
PROCESSOR (soldere	d on-board)	Intel® Celeron® J	J1900 2.00Ghz (2.30GHz Bur	st) • 4 cores / 4 threads • 2M	3 L2 cache • 22nm			
CHIPSET			Intel® Bay Trail • Include	d into processor chip (SoC)				
VIDEO CONTROLLER		Intel® HD	Graphics for Intel Atom® pro	ocessor Z3700 series • 688M	Hz/854MHZ			
SYSTEM MEMORY RAI	М		1GB or 2GB or 4GB or 80	BB SODIMM DDR3L module				
	CFast	1x bootable CFast SATA II slot onboard with external access (up to 240GB)						
MASS STORAGE	SSD mSATA	1x onboard	1x onboard connector for direct insertion of mSATA SSD SATA II (up to 960GB)					
	LAN		2x Gigabit E	thernet (RJ45)				
INTERFACES	USB	1x USB 3.0 (Type-A) • 1x USB 2.0 (Type-A)						
	VIDEO			-				
ADD-ON INTERFACES (optional)	Position A (max 1) only S0 version and BM	1x Wi-I	1x RS232/422/485 (DB15M) 2x RS232/4 2x RS232/422/485 1x USB 2 2x USB 2 1x Gigabit Ethernet (R Fi module (IEEE 802.11 a/b/o	15M) + 1x USB 2.0 (Type-A) isolated + 1x USB 2.0 (Type-/ 22/485 (DB9M) 5 optoisolated (DB9M) .0 (Type-A) 2.0 (Type-A) J45) + 1x USB 2.0 (Type-A) g/n/ac, 2.4GHz/5GHz • Blueto E Cat 4, GSM/GPRS, UMTS/H	ooth 4.2)			
POWER SUPPLY INPU	Т		24VDC (18÷3	2VDC)isolated				
	UPS			ery pack (Pb • 12V/2,5Ah) e mounting)				
POWER SUPPLY (optional)	ATX only S0 version and BM w/o UPS	Kit for ATX mode p	power supply (push button,	internal cable and connector	for remote control)			
	ATX only BM w/ UPS	-						
BATTERY			1x CR2032 I	nternal access				
O.S. CERTIFIED			Microsoft Windows Embed	7 Pro/Ultimate 32/64bit ded Standard 7E/7P 32/64 b Enterprise 2016/2019 64 bit	it			
OPERATING TEMPERA	ATURE		0°C	÷50°C				
STORAGE TEMPERAT	URE		-5°C	÷ 60°C				
OPERATING/STORAG	E RELATIVE HUMIDITY		20% ÷ 90% RH	(non-condensing)				
APPROVALS		CE RoHS UKCA cULus Listed						

QT2200 & HT2200



- TFT LCDs in 10.4", 12.1" and 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio and 10.1", 12.1", 15.6", 18.5", 21.5", 24" in Wide aspect ratio
- Aluminum (ALU), aluminum True Flat (TF) and stainless steel True Flat (TFX) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Intel® Celeron® processors of Bay Trail SoC generation
- RAM up to 8GB
- Built-in UPS with external battery pack (optional)
- Built-in supercapacitors μUPS, with 512kB MRAM for retentive data management (optional)
- Available in SL version with reduced depth, S0 version with the possibility to install additional interfaces and S1 version with PCI or PCIe expansion slot



*only TFM frontal







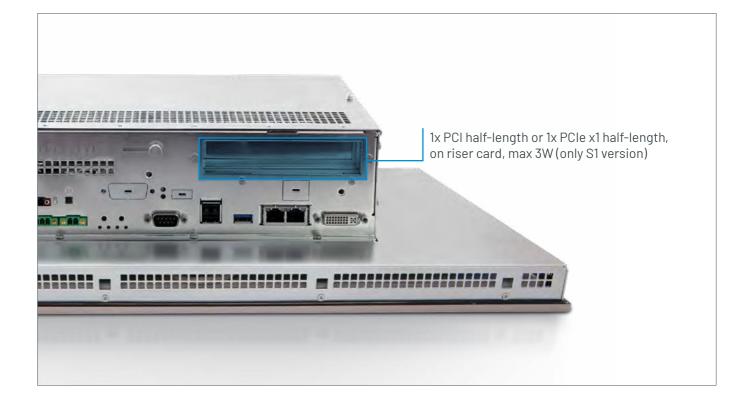
QT2200 & HT2200 - (SL Version)

QT2200 & HT2200 - (SO Version)



QT2200 & HT2200 - (S1 Version)

DETAIL - EXPANSION SLOTS



QT2200 & HT2200

TECHNICAL DATA

		QT2200 -ALU	QT2200 -TFM	HT2200 -ALU	HT2200 -TF	HT2200 -TFX		
LED BACKLIGHT TFT LCD		15.6" W - 15.6" W - 1 18.5" W - 18.5" W - 1 21.5" W - 1	15.6" W - 1920x1080			12.1" - 800x600 12.1" - 1024x768 15.0" - 1024x768 17" - 1280x1024 19" - 1280x1024		
CUT-OUT		Q	Т		HT			
FRONT USB		-	-	1x USB 2.0 prote	• •	-		
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch		Resistive 5 wires			
FRONT PANEL	Material	Aluminum	True Flat Aluminum	Aluminum	True Flat Aluminum	True Flat Stailness Steel		
	ASEM Logo	-	-	Adhesive label	Silk-scre	en printed		
PROTECTION	IP rating		IP65 -	frontal		IP66K - frontal		
GRADE	NEMA rating	UL Type 1, 4x	(indoor only)	UL Type 1, 4x (indoor only) and 12				
CASE	Installation			Panel mounting				
	Material			nc-coated skin pass st				
PROCESSOR (solder	red on-board)	Intel® Celeron®		Hz Burst) • 64bit • 4 co		_2 cache • 22nm		
VIDEO CONTROLLER	<u> </u>	Intol		Atom® processor Z370	• • • • • • • • • • • • • • • • • • • •	/ ₋ MU ₇		
WATCHDOG	`	ilitei	· · · · · · · · · · · · · · · · · · ·	ogrammable time peri		411112		
TPM				ete TPM 2.0 module (op				
SYSTEM MEMORY R	AM			GB or 8GB (1x SODIMM				
MASS STORAGE	Cfast	1x t	oootable CFast SATA II	slot onboard with exte	ernal access (up to 240	OGB)		
(SSD mSATA and SSD/HDD are	SSD mSATA	1x on	board connector for di	rect insertion of SSD r	mSATA SATA II (up to 9	60GB)		
alternative to each other)	SSD/HDD only SO/S1 versions	1x onl	board connectors for S	SDs/HDDs 2.5" SATA II	with internal installat	ion kit		
	LAN		2:	Gigabit Ethernet (RJ4	45)			
INTERFACES	USB		2x USB 2	.0 (Type-A) • 1x USB 3.0	(Type-A)			
	SERIAL			1x RS232 (DB9M)				
ADD-ON INTERFACES (optional)	Position A (max 1)	1x DVI-I (Resolution up to 1920x1080 • VGA adapter included) 1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232 (DB9M) 2x USB 2.0 (Type-A)						
not available for SL version	Position B (max 1)	1x Gigabit Ethernet (RJ45) 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Bluetooth 4.2)¹ and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)¹						
EXPANSION SLOTS	only S1 version	1x PCI half-length or 1x PCIe x1 half-length, on riser card, max 3W						
POWER SUPPLY INF	-	24VDC (18÷32VDC) isolated						
	UPS Backside mounting not available for SL version	ot UPS with external battery pack (Pb • 12V/2,5Ah)						
POWER SUPPLY (optional)	UPS + 512kB MRAM Backside mounting not available for SL version		UPS with external battery pack (Pb • 12V/2,5Ah) + 512kB MRAM (backside or separate mounting)					
	μUPS + 512kB MRAM		Superc	apacitors µUPS + 512k	B MRAM			
	ATX only S0/S1 versions	Kit for ATX m	ode power supply (pus	h button, internal cabl	e and connector for re	emote control)		

TECHNICAL DATA

	QT2200 -ALU	QT2200 -TFM	HT2200 -ALU	HT2200 -TF	HT2200 -TFX
BATTERY		1x	CR2032 Internal acce	SS	
O.S. CERTIFIED	Microsoft Wind		Windows 7 Pro/Ultima ws Embedded Standar 2016/2019 64bit (2019 v	d 7E/7P 32/64 bit	e with CODESYS)
OPERATING TEMPERATURE			0°C ÷ 50°C ex7 HDD or Intel® Core™ °C ÷ 45°C (Standard HD		
STORAGE TEMPERATURE			-10°C ÷ 60°C		
OPERATING/STORAGE RELATIVE HUMIDITY		20%	÷ 90% RH (non-conde	nsing)	
APPROVALS	CE				

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Wi-Fi and Cellular modules cannot be used if CODESYS SoftPLC control software is installed on the system.
 ATEX certification is ensured only without UPS, microUPS, power supply variants, UPS battery kit options and wireless modules

QT2250 & HT2250



- TFT LCDs in 10.4", 12.1", 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio and 7", 10.1", 12.1", 15.6", 18.5", 21.5", 24" in Wide aspect ratio
- Aluminum (ALU) and aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Stainless steel (AISI 304L) True Flat (TFK) front panel with resistive touchscreen
- Intel Atom® x5 and x7 processors of Apollo Lake SoC generation
- RAM up to 8GB
- Available in SL version with reduced depth and S0 version with the possibility to install additional interfaces















(only TFK frontal)



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		QT2250-ALU	QT2250-TFM	QT2250-TFK	HT2250-ALU	HT2250-TF		
LED BACKLIGHT TFT L	.CD		7" W - 800x480 10.1" W - 1280x800 12.1" W - 1280x800 15.6" W - 1366x768 15.6" W - 1920x1080 18,5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24" W - 1920x1080	10.4" - 800x600 12.1" - 800x600 12.1" - 1024x768 15" - 1024x768 17" - 1280x1024 19" - 1280x1024				
CUT-OUT			О Т НТ					
FRONT USB			-		1x USB 2.0 (Typ	e-A), protected		
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch		Resistive 5 wires			
FRONT PANEL	Material	Aluminum	True Flat Aluminum	True Flat Stainless Steel	Aluminum	True Flat Aluminum		
	ASEM Logo		-		Adhesive label	Silk screen printed		
PROTECTION GRADE	IP rating	IP65 - 1	frontal	IP69K - frontal	IP65 -	frontal		
PROTECTION GRADE	NEMA rating	UI	Type 1, 4x (indoor onl	y)	UL Type 1, 4x (in	door only) and 12		
CASE	Installation			Panel mounting				
CASE	Material		Zir	nc-coated skin pass st	eel			
PROCESSOR (soldered	d on-board)		-E3930 1.30Ghz (1.80Gł -E3950 1.60Ghz (2.00Gl					
CHIPSET			Intel® Apollo Lak	ke • Included into proce	essor chip (SoC)			
VIDEO CONTROLLER			HD Graphics 500 inte HD Graphics 505 inte	•				
TPM		Intel® PTT (TPM integrated) • Discrete TPM 2.0 module (optional)						
SYSTEM MEMORY	with x5-E3930	4GB LP-DDR4 module						
RAM	with x7-E3950		4GE	3 or 8GB LP-DDR4 mod	lule			
MASS STORAGE	CFast	1x b	ootable CFast SATA III	slot onboard with exte	rnal access (up to 240	GB)		
MASS STURAGE	M.2 SSD	1x onbo	oard connector for dire	ect insertion of M.2 224	42 SATA III SSD (up to 4	+80GB)		
	LAN		2x	Gigabit Ethernet (RJ4	5)			
INTERFACES	USB			3x USB 3.0 (Type-A)				
	VIDEO			1x DisplayPort++ V1.2				
ADD-ON INTERFACES (optional)	Position A (max 1) only S0 version and BM		2x RS232 1x RS232/422 1x RS232/422/48	RS232/422/485 (DB9I 2/422/485 optoisolater 2/485 (DB15M) + 1x USB 5 (DB15M) isolated + 1x 2x USB 2.0 (Type-A) nernet (RJ45) + 1x USB	d (DB9M) 2.0 (Type-A) USB 2.0 (Type-A)			
POWER SUPPLY INPU	Г		24	VDC (18÷32VDC) isolate	ed			
POWER SUPPLY	UPS			rnal battery pack (NiM side or separate mour				
(optional)	ATX only S0 version and BM	Kit for ATX mode power supply (push button, internal cable and connector for remote control)						
BATTERY		1x CR2032 Internal access						
O.S. CERTIFIED		Microsoft Windows 10 IoT Enterprise 2019 64 bit						
OPERATING TEMPERA	TURE	0°C ÷ 50°C						
STORAGE TEMPERATU	JRE	-5°C ÷ 60°C						
OPERATING/STORAGE	RELATIVE HUMIDITY	1TY 20% ÷ 90% RH (non-condensing)						
APPROVALS				CE RoHS UKCA cULus Listed				

QT3400/3600 & HT3400/3600



- TFT LCDs in 12.1" and 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio and 12.1", 15.6", 18.5", 21.5", 24" in Wide aspect ratio
- Aluminum (ALU) and aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Stainless steel True Flat (TFX) front panels with resistive touchscreen
- Intel® Celeron®, Core™ i3, i5, i7 processors of Skylake and Kaby Lake generation
- RAM up to 32GB
- Built-in UPS with external battery pack (optional)
- Built-in supercapacitors µUPS, with 512kB MRAM for retentive data management (optional)
- Available in S0, S1 and S2 version, with possibility to install additional interfaces, PCI/PCIe expansion slots and extractable drives slots for 2,5" SSDs/HDDs
- Available with additional RVL (Remote Video Link) interface for remotation of the DVI-D and USB 2.0 signals up to 100m (optional)

GALLERY





QT3400/3600 & HT3400/3600 - (S0 Version)

QT3400/3600 & HT3400/3600 - (S1 Version)



QT3400/3600 & HT3400/3600 - (D2 Version)

DETAIL - EXTRACTABLE DRIVES SLOT



COMPARISON TABLE

	QT3400/3600 & HT3400/3600					
	S0	S1	D2			
ADD-ON INTERFACES (optional)	✓	✓	✓			
EXPANSION SLOTS PCI/PCIe	X	1	×			
INTERNAL INSTALLATION KIT for SSDs/HDDs 2,5" SATA III	1	1	X			
EXTRACTABLE DRIVES SLOT for SSDs/HDDs 2.5" SATA III	X	X	2			



(only TFX frontal)

CODESYS OPTIONAL

RVL OPTIONAL

CE (ROHS)

FANLESS

QT3400/3600 & HT3400/3600

TECHNICAL DATA

		QT3400/3600 -ALU	QT3400/3600 -TFM	HT3400/3600 -ALU	HT3400/3600 -TF	HT3400/3600 -TFX
LED BACKLIGHT TFT L	CD	15.6" W - 1366x768 15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24"W - 1920x1080		12.1" - 800x600 12.1" - 1024x768 12.1" W - 1280x800 (not for D2 version) 15" - 1024x768 15.6" W - 1366x768 15.6" W - 1920x1080 17" - 1280x1024 18.5" W - 1366x768 18.5" W - 1920x1080 19" - 1280x1024 21.5" W - 1920x1080 24"W - 1920x1080		12.1" - 800x600 12.1" - 1024x768 15.0" - 1024x768 17" - 1280x1024 19" - 1280x1024
CUT-OUT		Ç	T		HT	
FRONT USB			_	1 x USB 2.0 (Typ	e-A), protected	-
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch		Resistive 5 wires	
FRONT PANEL	Material	Aluminum	True Flat Aluminum	Aluminum	True Flat Aluminum	True Flat Stainless Steel
	ASEM Logo		-	Adhesive label	Silk-scre	en printed
PROTECTION GRADE	IP rating		IP65 -	frontal		IP66K - frontal
	NEMA rating	UL Type 1, 4x	(indoor only)	UL T	ype 1, 4x (indoor only) a	and 12
CASE	Installation			Panel mounting		
	Material		Ziı	nc-coated skin pass st	eel	
PROCESSOR (soldered on-board)	xx3400	Intel® Celeron® G3900E 2.40GHz 64bit • 2 cores / 2 threads • 2MB Smart cache • 14nm Intel® Core™ i3-6100E 2.70GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-6440EQ 2.70GHz (3.40GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm Intel® Core™ i7-6820EQ 2.80GHz (3.50GHz Turbo) 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm				
(soldered on-board)	xx3600	Intel® Core™ i5-7	ore™ i3-7100E 2.90GHz 440EQ 2.90GHz (3.60G 820EQ 3.00GHz (3.70G	Hz Turbo) 64bit • 4 cor	es / 4 threads • 6MB Sr	nart cache • 14nm
	xx3400	Inte	el® HM170 PCH (Platforn	n Controller Hub) with	integrated RAID contr	oller
CHIPSET	xx3600	Inte	el® HM175 PCH (Platforn	n Controller Hub) with	integrated RAID contr	oller
	S2 version with 2x PCle x4			-		
VIDEO CONTROLLER	xx3400	Intel® I	HD Graphics 510 integr HD Graphics 530 integr I Graphics 530 integrat	ated in Intel® Core™ i3	processor • 350MHz/9	950MHz
	xx3600		HD Graphics 630 integr Graphics 630 integrat			
WATCHDOG			Pr	ogrammable time per	iod	
ТРМ			Intel® PTT (TPM integ	grated) • Discrete TPM	2.0 module (optional)	
SYSTEM MEMORY RAM	I	4GB (1x 4GB SODIMM DDR4 module) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module)				
	Cfast	1x b	ootable CFast SATA III	slot onboard with ext	ernal access (up to 240	OGB)
MASS STORAGE	SSD mSATA	1x ont	ooard connector for di	ect insertion of SSD n	nSATA SATA III (up to 9	60 GB)
	SSD/HDD	1x onboard connector for SSD/HDD 2,5" SATA III with internal installation kit				
EXTRACTABLE	only D1 version			-		
MASS STORAGE	only D2 version		2x extracta	able SSDs/HDDs 2.5" S	ATA III units	
RAID	only D2 version and BM S2 D0 version			Raid 0, 1		

TECHNICAL DATA

		QT3400/3600 -ALU	QT3400/3600 -TFM	HT3400/3600 -ALU	HT3400/3600 -TF	HT3400/3600 -TFX
	LAN	4x Gigabit Ethernet (RJ45)				
	USB		3x USB 3.	.0 (Type-A) • 2x USB 2.0	O(Type-A)	
INTERFACES	SERIAL			1x RS232 (DB9M)		
	VIDEO		1x DVI-I	D (Resolution up to 192	(0x1080)	
ADD-ON INTERFACES	Position A (max 1)		1x RS232/422/48 2x	2/485 (DB15M) + 1x USB 15 (DB15M) isolated + 1x x RS232/422/485 (DB9 2/422/485 optoisolate 2x USB 2.0 (Type-A)	(USB 2.0 (Type-A)	
(optional)	Position B (max 1)				45) Hz/5GHz • Bluetooth 4.	
EXPANSION SLOTS	only S1 version		1x PCI half-length or 1	lx PCle x4 half-length,	on riser card, max 5W	
EXPANSION SLUTS	only S2 version			-		
POWER SUPPLY INPU	Т		24	+VDC (18÷32VDC) isolat	ted	
	UPS	UPS with external battery pack (Pb • 12V/2.5Ah) (backside or separate mounting)				
POWER SUPPLY (optional)	UPS + 512kB MRAM	-				
(optional)	μUPS + 512kB MRAM		Superc	apacitors µUPS + 512k	B MRAM	
	ATX	Kit for ATX m	ode power supply (pus	h button, internal cabl	e and connector for re	mote control)
BATTERY			1x	CR2032 Internal acce	ess	
O.S. CERTIFIED	xx3400		Microsoft \	ows 10 IoT Enterprise : Windows 7 Pro/Ultima ws Embedded Standar	te 32/64 bit	
	xx3600		Microsoft Wind	ows 10 IoT Enterprise	2019/2016 64 bit	
OPERATING	without forced ventilation			0°C ÷ 50°C 4x7 HDD or Intel® Core™ °C ÷ 45°C (Standard HE		
TEMPERATURE	with forced ventilation (only S2 version)	on -				
STORAGE TEMPERATU	JRE			-10°C ÷ 60°C		
OPERATING/STORAGE	E RELATIVE HUMIDITY	VE HUMIDITY 20% ÷ 90% RH (non-condensing)				
FORCED VENTILATION	(optional)	-				
APPROVALS		CE				

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Wi-Fi and Cellular modules cannot be used if CODESYS SoftPLC control software is installed on the system.
 ATEX certification is ensured only without UPS, microUPS, power supply variants, UPS battery kit options and wireless modules.
 MicroUPS+512kB MRAM is not compatible with 2x HDD/SSD option for BM3400/3600 S0 D2

QT3500 & HT3500



- TFT LCDs in 12.1" and 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio and 12.1", 15.6", 18.5", 21.5", 24" in Wide aspect ratio
- · Aluminum (ALU) and aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Stainless steel True Flat (TFX) front panels with resistive touchscreen
- Intel® Celeron®, Core™ i3, i5, i7 processors of Kaby Lake generation
- RAM up to 16GB
- Built-in UPS with external battery pack (optional)
- Available in SL version with reduced depth, S0 version with the possibility to install additional interfaces and S1 version with one PCI or PCIe expansion slot
- Available with additional RVL (Remote Video Link) interface for remotation of the DVI-D and USB 2.0 signals up to 100m (optional)

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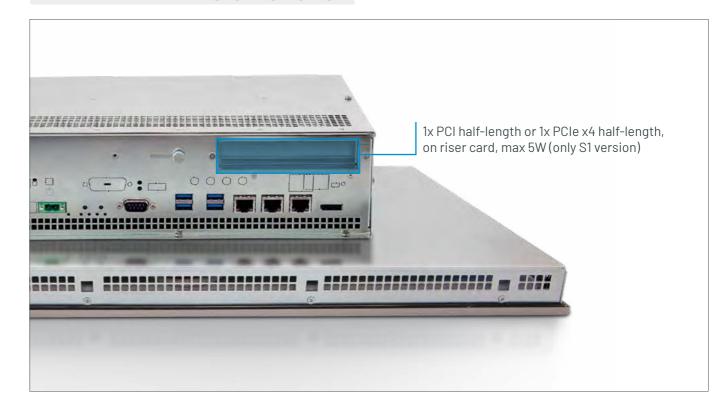
QT3500 & HT3500 - (SL Version)

QT3500 & HT3500 - (S0 Version)



QT3500 & HT3500 - (S1 Version)

DETAIL - EXPANSION SLOTS



QT3500 & HT3500

TECHNICAL DATA

		QT3500 -ALU	QT3500 -TFM	HT3500 -ALU	HT3500 -TF	HT3500 -TFX
LED BACKLIGHT TFT I	_CD	15.6" W - 1366x768 15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24"W - 1920x1080		12.1" - 800x600 12.1" - 1024x768 12.1" W - 1280x800 15" - 1024x768 15.6" W - 1366x768 15.6" W - 1920x1080 17" - 1280x1024 18.5" W - 1366x768 18.5" W - 1920x1080 19" - 1280x1024 21.5" W - 1920x1080		12.1" - 800x600 12.1" - 1024x768 15" - 1024x768 17" - 1280x1024 19" - 1280x1024
CUT-OUT		Ç	T		HT	
FRONT USB			-	1 x USB 2.0 (Typ	e-A), protected	-
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch	Resistiv	e 5 wires	Resistive 5 wires
FRONT PANEL	Material	Aluminum	True Flat Aluminum	Aluminum	True Flat Aluminum	True Flat Stainless Steel
	ASEM Logo		-	Adhesive label	Silk-screen printed	Silk-screen printed
DDOTFOTION OD 1	IP rating		IP65 - 1	frontal		IP66K - frontal
PROTECTION GRADE	NEMA rating	UL Type 1, 4x	(indoor only)	UL T	ype 1, 4x (indoor only) a	and 12
0405	Installation			Panel mounting		
CASE	Material		Ziı	nc coated stainless st	eel	
PROCESSOR (soldered	d on-board)	Intel® Co Intel® Core™ i5-7	ore™ i3-7100U 2.40GHz ′300U 2.60GHz (3.50GF	20GHz 64bit • 2 cores / 2 threads • 2MB Smart cache • 14nm 40GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm .50GHz Turbo) 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm .90GHz Turbo) 64bit • 2 cores / 4 threads • 4MB Smart cache • 14nm		
CHIPSET		Intel® Ka	by Lake U PCH (Platfor	m Controller Hub) • Inc	cluded into processor o	chip (SoC)
VIDEO CONTROLLER		Intel® HD Graphics 610 integrated in Intel® Celeron® processor • 300MHz/900MHz Intel® HD Graphics 620 integrated in Intel® Core™ i3 processor • 300MHz/1GHz Intel® HD Graphics 620 integrated in Intel® Core™ i5 processor • 300MHz/1.10GHz Intel® HD Graphics 620 integrated in Intel® Core™ i7 processor • 300MHz/1.15GHz				/1GHz I.10GHz
WATCHDOG			Pr	ogrammable time per	iod	
ТРМ	Discrete version only for SO/S1 versions and BM		Intel® PTT (TPM integ	grated) • Discrete TPM	2.0 module (optional)	
SYSTEM MEMORY RAN	1		4GB or 8GB	or 16GB (1x SODIMM DI	DR4 module)	
	Cfast	1x t	oootable CFast SATA III	slot onboard with ext	ernal access (up to 240	OGB)
	SSD mSATA			-		
MASS STORAGE	SSD M.2	1x onboard connec		of M.2 2280 NVMe PC PCIe x4 SSD (up to 1TB 242 SATA III SSD (up to)1) or M.2 2280 NVMe
	SSD/HDD only S0/S1 versions and BM	1x o	nboard connector for S	SSD/HDD 2.5" SATA III v	with internal installatio	n kit
	LAN		3x	Gigabit Ethernet (RJ	45)	
INTERFACES	USB	SB 4x USB 3.0 (Type-A)				
	SERIAL					
	VIDEO	1x DisplayPort++ V1.2 1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A)				
ADD-ON INTERFACES (optional)	Position A (max 1)					
not available for SL version	Position B (max 1)		1x DVI-E		l0x1200) VL Hz/5GHz • Bluetooth 4.	

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		QT3500 -ALU	QT3500 -TFM	HT3500 -ALU	HT3500 -TF	HT3500 -TFX	
EXPANSION SLOTS	only S1 version		1x PCI half-length or 1	lx PCIe x4 half-length,	on riser card, max 5W		
POWER SUPPLY INPUT	·	24VDC(18÷32VDC)isolated					
POWER SUPPLY	UPS			kternal battery pack (Pl kside or separate mour			
(optional)	ATX only SO/S1 versions	Kit for ATX m	ode power supply (pus	h button, internal cabl	e and connector for re	mote control)	
BATTERY			1>	CR2032 internal acce	SS		
O.S. CERTIFIED			Microsoft Wind	ows 10 IoT Enterprise 2	2019/2016 64 bit		
OPERATING TEMPERA	TURE			0°C ÷ 50°C ax7 HDD or Intel® Core™ °C ÷ 45°C (Standard HD			
STORAGE TEMPERATU	IRE			-10°C ÷ 60°C			
OPERATING/STORAGE	RELATIVE HUMIDITY	20% ÷ 90% RH(non-condensing)					
APPROVALS CE RoHS UKCA cULus Listed							

^{1.} The M.2 NVMe PCIe x4 SSDs show actual performance that differs from the manufacturer's claims, as they are driven via 2 lanes (socket M.2 PCIe x2). Data transfer rates are about half of the declared value (comparable to M.2 NVMe PCIe x2 SSDs).

QT5400/5600 & HT5400/5600



- TFT LCDs in 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio and 15.6", 18.5", 21.5", 24" in Wide aspect ratio
- · Aluminum (ALU) and aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Stainless steel True Flat (TFX) front panels with resistive touchscreen
- Intel® Celeron®, Core™ i3, i5, i7 processors of Skylake and Kaby Lake generation
- RAM up to 32GB
- Available in S0 version with the possibility to install additional interfaces, S1 version with one PCle expansion slot and S3 version with three PCle
- Available with additional RVL interface for remotation of the DVI-D and USB 2.0 signals up to 100m (optional)
- Available with 115/230VAC power supply (optional)

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GALLERY



QT5400/5600 e HT5400/5600 - (S0 Version) - 24VDC



QT5400/5600 e HT5400/5600 - (S0 Version) - 230VAC



QT5400/5600 e HT5400/5600 - (S1 Version) - 24VDC



QT5400/5600 e HT5400/5600 - (S1 Version) - 230VAC



QT5400-5600, HT5400-5600 - (S3 Version) - 24VDC



QT5400-5600, HT5400-5600 - (S3 Version) - 230VAC

DETAIL - EXTRACTABLE DRIVES SLOT



QT5400/5600 & HT5400/5600

TECHNICAL DATA

		QT5400/5600 -ALU	QT5400/5600 -TFM	HT5400/5600 -ALU	HT5400/5600 -TF	HT5400/5600 -TFX	
LED BACKLIGHT TFT L	CD	15.6" W - 1 18.5" W - 18.5" W - 1 21.5" W - 1	15.6" W - 1366x768 15.6" W - 1366x768 15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24"W - 1920x1080 24"W - 1920x1080 24"W - 1920x1080		15" - 1024x768 17" - 1280x1024 19" - 1280x1024		
CUT-OUT		Q	Т		НТ		
FRONT USB		-	-	1x USB 2.0 (Type	e-A), protected	-	
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch		Resistive 5 wires		
FRONT PANEL	Material	Aluminum	True Flat Aluminum	Aluminum	True Flat Aluminum	True Flat Stainless Steel	
	ASEM Logo	-	-	Adhesive label	Silk scree	en printed	
PROTECTION GRADE	IP rating		IP65 -	frontal		IP66K - frontal	
TROTECTION ORABE	NEMA rating	UL Type 1, 4x	(indoor only)	UL Ty	/pe 1, 4x (indoor only) a	nd 12	
CASE -	Installation			Panel mounting			
CASE	Material		Zir	nc-coated skin pass st	eel		
PROCESSOR	xx5400	Intel® Core™ i3-6100 3.70GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-6500 3.20GHz (3.60GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm Intel® Core™ i7-6700 3.40GHz (4.00GHz Turbo) 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm					
(soldered on-board)	xx5600	Intel® C Intel® Core™ i5-	Intel® Celeron® G3930E 2.90Ghz 64bit • 2 cores / 2 threads • 2MB Smart cache • 14nm Intel® Core™ i3-7101E 3.90Ghz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-7500 3.40Ghz (3.80GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm Intel® Core™ i7-7700 3.60Ghz (4.20GHz Turbo) 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm				
CHIPSET		Inte	el® C236 PCH (Platform	Controller Hub) with i	ntegrated RAID contro	ller	
_	xx5400		Graphics 530 integrate HD Graphics 530 integ		•		
VIDEO CONTROLLER	xx5600	Intel® HD (HD Graphics 610 integ Graphics 630 integrate HD Graphics 630 integ	d in Intel® Core® i3 and	i5 processors • 350MH	Hz/1.10GHz	
TPM			Intel® PTT (TPM integ	rated) • Discrete TPM	2.0 module (optional)		
SYSTEM MEMORY RAM			8GB (2: 16GB (2	x 4GB SODIMM DDR4 m x 4GB SODIMM DDR4 m x 8GB SODIMM DDR4 n x 16GB SODIMM DDR4 l	nodule) nodule)		
-	CFast	1x b	ootable CFast SATA III	slot onboard with exte	ernal access (up to 240	GB)	
MASS STORAGE	SSD M.2	SSD M.2 1x onboard connector for direct insertion of M.2 2280 NVMe PCIe x4 SSD (up to 512GB) of SSD (up to 480GB)					
	SSD/HDD	2x onboard connectors for SSDs/HDDs 2.5" SATA III with internal installation kit					
EXTRACTABLE	S0/S1/S3 versions	s 1x extractable SSD/HDD 2.5" SATA III unit					
MASS STORAGE	only S1/S3 versions	2x extractable SSDs/HDDs 2.5" SATA III units					
RAID		Raid 0, 1					
	LAN		4x	Gigabit Ethernet (RJ4	5)		
INTERFACES	USB			4x USB 3.0 (Type-A)			
INTERI ACES	SERIAL			1x RS232 (DB9M)			
	VIDEO		1x DVI-E	(Resolution up to 192	0x1080)		

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		QT5400/5600 -ALU	QT5400/5600 -TFM	HT5400/5600 -ALU	HT5400/5600 -TF	HT5400/5600 -TFX
ADD-ON INTERFACES	Position A (max 1)	1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232/422/485 (DB9M) 2x RS232/422/485 optoisolated (DB9M) 2x USB 2.0 (Type-A)				
(optional)	Position B (max 1)	2v HighlavPort + V12				
_	only S1 version		1x PCle x16 i	nalf-length, on riser ca	rd, max 75W	
EXPANSION SLOTS	only S3 version	1x PCIe x16 half-length + 1xPCIe x4 half-length, on riser card, max 75W 1x PCIe x16 half-length + 1xPCIe x4 half-length + 1xPCIe x1 half-length, on riser card, max 80W 2x PCIe x8 half-length + 1x PCIe x4 half-length, on riser card, max 85W 3x PCI half-lenght, on riser card, max 30W 2x PCI half-lenght + 1x PCIe x4 half-lenght, on riser card, max 35W				
POWER SUPPLY		24VDC(18÷32VDC) isolated				
INPUT optional 115V/230VAC (85÷264VAC) isolated,				autoranging	autoranging	
POWER SUPPLY (optional)	ATX	Kit for ATX mode power supply (push button, internal cable and connector for remote control)				
BATTERY		1x CR2032 Internal access				
xx5400 0.S. CERTIFIED		Microsoft Windows 10 IoT Enterprise 2019 64 bit Microsoft Windows 7 Pro/Ultimate 64 bit Microsoft Windows Embedded Standard 7E/7P 64 bit Microsoft Windows Server Embedded Standard 2019 R2 64 bit				
	xx5600			ndows 10 IoT Enterpris Server Embedded Sta		
OPERATING TEMPERATURE		0°C ÷ 50°C 0°C ÷ 45°C (24x7 HDD or Intel® Core™ i7 processor) 5°C ÷ 45°C (Standard HDD)				
STORAGE TEMPERATURE		-10°C ÷ 60°C				
OPERATING/STORAGE	RELATIVE HUMIDITY		20%	÷ 90% RH (non-conder	nsing)	
APPROVALS		CE RoHS UKCA cULus Listed				

COMPARISON **TABLE**

		QT2150 & HT2150	QT2200 & HT2200	QT2250 & HT2250	QT3400 & HT3400	QT3500 & HT3500	QT3600 & HT3600	QT5400 & HT5400	QT5600 & HT5600
FANLESS		✓	✓	✓	✓	✓	✓	Х	Х
	Wide sizes	7", 10,1", 12,1", 15,6"	10,1", 12,1", 15,6", 18,5", 21,5", 24"	7", 10,1", 12,1", 15,6", 18,5", 21,5", 24"	12,1", 15,6", 18,5", 21,5", 24"	12,1", 15,6", 18,5", 21,5", 24"	12,1", 15,6", 18,5", 21,5", 24"	15,6", 18,5", 21,5", 24"	15,6", 18,5", 21,5", 24"
FRONT	Narrow sizes	8,4", 10,4", 12,1", 15"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"
PANELS	Types	ALU, TF, TFM	ALU, TF, TFM, TFX	ALU, TF, TFM, TFK	ALU, TF, TFM, TFX	ALU, TF, TFM, TFX	ALU, TF, TFM, TFX	ALU, TF, TFM, TFX	ALU, TF, TFM, TFX
	Touchscreen technology	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch
PROCESSORS	Model	Intel® Celeron® J1900	Intel® Celeron® J1900	Intel Atom® x5-E3930 Intel Atom® x7-E3950	Intel® Celeron® G3900E Intel® Core™ i3-6100E Intel® Core™ i5-6440EQ Intel® Core™ i7-6820EQ	Intel® Celeron® 3965U Intel® Core™ i3-7100U Intel® Core™ i5-7300U Intel® Core™ i7-7600U	Intel® Core™ i3-7100E Intel® Core™ i5-7440EQ Intel® Core™ i7-7820EQ	Intel® Core™ i3-6100 Intel® Core™ i5-6500 Intel® Core™ i7-6700	Intel® Celeron® G3930E Intel® Core™ i3-7101E Intel® Core™ i3-7101E Intel® Core™ i7-7700
	Generation	Intel® Bay Trail	Intel® Bay Trail	Intel® Apollo Lake	Intel® Skylake	Intel® Kaby Lake U	Intel® Kaby Lake	Intel® Skylake	Intel® Kaby Lake
SYSTEM MEMOR	RY	Up to 8GB	Up to 8GB	Up to 8GB	Up to 32GB	Up to 16GB	Up to 32GB	Up to 32GB	Up to 32GB
	LAN	2x RJ45	2x RJ45	2x RJ45	4x RJ45	3x RJ45	4x RJ45	4x RJ45	4x RJ45
	USB	1x USB 3.0 • 1x USB 2.0	2x USB 2.0 • 1x USB 3.0	3x USB 3.0	3x USB 3.0 • 2x USB 2.0	4x USB 3.0	3x USB 3.0 • 2x USB 2.0	4x USB 3.0	4x USB 3.0
INTERFACES	Serial	-	1x RS232 (DB9M)	-	1x RS232 (DB9M)	1x RS232 (DB9M)	1x RS232 (DB9M)	1x RS232 (DB9M)	1x RS232 (DB9M)
	Video	-	1x DVI-D	1x DisplayPort++ V1.2	1x DVI-D	1x DisplayPort++ V1.2	1x DVI-D	1x DVI-D	1x DVI-D
EXPANSION SL	OTS PCI/PCIe	-	Up to 1	-	Up to 1	Up to 1	Up to 1	Up to 3	Up to 3
INTERNAL SSD	/HDD	-	Up to 1	-	Up to 1	Up to 1	Up to 1	Up to 3	Up to 3
EXTRACTABLE	SSD/HDD	-	-	-	Up to 2	-	Up to 2	Up to 2	Up to 2
POWER SUPPLY	Y INPUT	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC 115V/230VAC	24VDC 115V/230VAC
OPERATING SYS	STEMS	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC Microsoft Windows Server Embedded Standard	Microsoft Windows 10 IoT Enterprise LTSC Microsoft Windows Server Embedded Standard
PAC VERSION *		X	√	X	√	X	√	X	X
CERTIFICATION	ıs	C E JUK CHUS LISTED	CE SX**	CE UK CH CH CH	CE UK CK	CE SUSTEE	CE LEX	CE UK CH CH CH	C E S UKA

 $^{^{\}ast}$ with UPS + 512kB MRAM for retentive data management and Codesys software ** only for QT-TFM



PB2150 & BM2150



- Intel® Celeron® processor of SoC Bay Trail generation
- RAM up to 8GB
- DIN rail mounting available (only BM2150)
- Built-in UPS with external battery pack (optional)
- Available in SL version with reduced depth and S0 version with the possibility to install additional interfaces (only PB2150)









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		PB2150	BM2150		
PROTECTION GRADE NEMA rating		IP2	20		
		-			
	Installation	Wall mounting	Book/DIN mounting		
CASE	Material	Zinc-coated skin pass steel	Aluminum alloy		
PROCESSOR (soldered	on-board)	Intel® Celeron® J1900 2.00Ghz (2.30GHz Burst	t) • 4 cores / 4 threads • 2MB L2 cache • 22nm		
CHIPSET		Intel® Bay Trail • Included into processor chip (SoC)			
VIDEO CONTROLLER		Intel® HD Graphics for Intel Atom® proc	essor Z3700 series • 688MHz/854MHZ		
SYSTEM MEMORY RAM		1GB or 2GB or 4GB or 8GE	SODIMM DDR3L module		
	CFast	1x bootable CFast SATA II slot onboar	d with external access (up to 240GB)		
MASS STORAGE	SSD mSATA	1x onboard connector for direct insertion	on of mSATA SSD SATA II (up to 960GB)		
	LAN	2x Gigabit Eth	nernet (RJ45)		
INTERFACES	USB	1x USB 3.0 (Type-A) •	1x USB 2.0 (Type-A)		
-	VIDEO	1x DVI-D (Resolutio	on up to 1920x1080)		
ADD-ON INTER- FACES (optional)	Position A (max 1) only SO version and BM	1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232/422/485 (DB9M) 2x RS232/422/485 optoisolated (DB9M) 1x USB 2.0 (Type-A) 2x USB 2.0 (Type-A) 1x Gigabit Ethernet (RJ45) + 1x USB 2.0 (Type-A) 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Bluetooth 4.2) and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)			
POWER SUPPLY INPUT		24VDC (18÷32VDC) isolated			
	UPS	UPS with external battery pack (Pb • 12V/2,5Ah) (separate mounting)			
POWER SUPPLY (optional)	ATX only S0 version and BM w/o UPS	Kit for ATX mode power supply (push button, internal cable and connector for remote control)			
	ATX only BM w/ UPS	-	Kit for ATX mode power supply (connector for remote control)		
BATTERY		1x CR2032 Int	ernal access		
O.S. CERTIFIED		Microsoft Windows 7 Pro/Ultimate 32/64bit Microsoft Windows Embedded Standard 7E/7P 32/64 bit Microsoft Windows 10 IoT Enterprise 2016/2019 64 bit			
OPERATING TEMPERAT	TURE	0°C ÷ 50°C			
STORAGE TEMPERATURE		-5°C ÷ 60°C			
OPERATING/STORAGE RELATIVE HUMIDITY		20% ÷ 90% RH (n	on-condensing)		
APPROVALS		CE RoHS UKCA cULus Listed			

PB2200 & BM2200



- Intel® Celeron® processors of SoC Bay Trail generation
- RAM up to 8GB
- Built-in UPS with external battery pack (optional)
- Available in SL version with reduced depth, S0 version with the possibility to install additional interfaces and S1 version with PCI or PCIe expansion slot (only PB2200)
- Available in RVL version (BM2200 RVL) for the remotation of the DVI-D and USB 2.0 signals up to 100m





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		PB2200	BM2200			
IP rating		li e	P20			
PROTECTION GRADE	NEMA rating	-				
	Installation	Wall mounting	Book mounting			
CASE Material		Zinc-coated skin pass steel	Aluminum alloy			
PROCESSOR (soldered	d on-board)	Intel® Celeron® J1900 2.00GHz (2.42GHz Burst)	• 64bit • 4 cores / 4 threads • 2MB L2 cache • 22nm			
CHIPSET		Intel® Bay Trail • Included into processor chip (SoC)				
VIDEO CONTROLLER		Intel® HD Graphics for Intel Atom® processor Z3700 series • 688MHz/854MHz				
WATCHDOG		Programmal	ble time period			
TPM		Discrete TPM 2.0) module (optional)			
SYSTEM MEMORY RAM	1	1GB or 2GB or 4GB or 8GB (1x SODIMM DDR3L module)	2GB or 4GB or 8GB (1x SODIMM DDR3L module)			
MASS STORAGE	Cfast	1x bootable CFast SATA II slot onboa	ard with external access (up to 240GB)			
SSD mSATA and	SSD mSATA	1x onboard connector for direct insert	tion of SSD mSATA SATA II (up to 960GB)			
SSD/HDD are alter- native to each other)	SSD/HDD only SO/S1 versions	1x onboard connectors for SSDs/HDDs	s 2.5" SATA II with internal installation kit			
	LAN	2x Gigabit E	thernet (RJ45)			
	USB	2x USB 2.0 (Type-A) • 1x USB 3.0 (Type-A)	2x USB 2.0 (Type-A) • 1x USB 3.0 (Type-A) front			
INTERFACES	SERIAL	1x RS232 (DB9M)	-			
	VIDEO	1x DVI-I (Resolution up to 1920x1080 • VGA adapter included)	1x DVI-I (Resolution up to 1920x1080 • VGA adapter included) or 1x RJ45 connector for RVL			
ADD-ON INTERFACES (optional) not available for SL version	Position A (max 1)	1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232 (DB9M) 2x USB 2.0 (Type-A)	1x RS232/422/485 (DB15M) isolated + 2x RS232(DB9M) 1x RS232/422/485 (DB15M) isolated + 1x Gigabit Ethernet (RJ45)			
	Position B (max 1)	1x Gigabit Ethernet (RJ45) 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/ 5GHz • Bluetooth 4.2)1 and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)1	-			
EXPANSION SLOTS	only S1 version	1x PCI half-length or 1x PCIe x1 half-length, on riser card, max 3W	-			
POWER SUPPLY INPUT	Г	24VDC (18÷32VDC) isolated				
	UPS Backside mounting not available for SL version	UPS with external battery pack (Pb • 12V/2,5Ah) (backside or separate mounting)	UPS with external battery pack (Pb • 12V/2,5Ah) (separate mounting)			
POWER SUPPLY (optional)	UPS + 512kB MRAM Backside mounting not available for SL version	UPS with external battery pack (Pb • 12V/2,5Ah) + 512kB MRAM (backside or separate mounting)	UPS with external battery pack (Pb • 12V/2,5Ah) + 512kB MRAM (separate mounting)			
	μUPS + 512kB MRAM	Supercapacitors	μUPS + 512kB MRAM			
	ATX only SO/S1 versions	Kit for ATX mode power supply (push button, inter- nal cable and connector for remote control)	-			
BATTERY		1x CR2032 Internal access	1x CR2032 Removable front access			
O.S. CERTIFIED		Microsoft Windows 7 Pro/Ultimate 32/64bit Microsoft Windows Embedded Standard 7E/7P 32/64 bit Microsoft Windows 2016/2019 64bit (2019 version not compatible with CODESYS)				
OPERATING TEMPERATURE		0°C ÷ 50°C 0°C ÷ 45°C (24×7 HDD or Intel® Core™ i7 processor) 5°C ÷ 45°C (Standard HDD)				
STORAGE TEMPERATU	JRE	-10°C ÷ 60°C				
OPERATING/STORAGE	RELATIVE HUMIDITY	20% ÷ 90% RH	(non-condensing)			
APPROVALS		CE RoHS UKCA UL 508	CE RoHS UKCA cULus Listed			

^{1.} Wi-Fi and Cellular modules cannot be used if CODESYS SoftPLC control software is installed on the system.

PB2250 & BM2250



- Intel Atom® x5 e x7 processor of SoC Apollo Lake generation
- RAM up to 8GB
- DIN rail mounting available (only BM2250)
- Available in SL version with reduced depth and S0 version with the possibility to install additional interfaces (only PB2250)









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		PB2250	BM2250				
IP rating		IP20					
PROTECTION GRADE	NEMA rating	-					
	Installation	Wall mounting	Book/DIN mounting				
CASE	Material	Zinc-coated skin pass steel	Aluminum alloy				
PROCESSOR (soldered	l on-board)	Intel Atom® x5-E3930 1.30Ghz (1.80Ghz Burst) • 64bit • 2 cores / 2 threads • 2MB L2 cache • 14nm Intel Atom® x7-E3950 1.60Ghz (2.00Ghz Burst) • 64bit • 4 cores / 4 threads • 2MB L2 cache • 14nm					
CHIPSET		Intel® Apollo Lake • Include	ed into processor chip (SoC)				
VIDEO CONTROLLER			:5-E3930 processor • 400MHz/550MHZ :7-E3950 processor • 500MHz/650MHZ				
TPM		Intel® PTT (TPM integrated) • Dis	screte TPM 2.0 module (optional)				
SYSTEM MEMORY	with x5-E3930	4GB LP-DI	DR4 module				
RAM	with x7-E3950	4GB or 8GB LI	P-DDR4 module				
MASS STORAGE	CFast	1x bootable CFast SATA III slot onboa	rd with external access (up to 240GB)				
MASS STURAGE	M.2 SSD	1x onboard connector for direct insertion of M.2 2242 SATA III SSD (up to 480GB)					
	LAN	2x Gigabit Ethernet (RJ45)					
INTERFACES	USB	3x USB 3.0 (Type-A)					
	VIDEO	1x DisplayPort++ V1.2					
ADD-ON INTERFACES (optional)	Position A (max 1) only S0 version and BM	2x RS232/422/485 (DB9M) 2x RS232/422/485 optoisolated (DB9M) 1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x USB 2.0 (Type-A) 1x Gigabit Ethernet (RJ45) + 1x USB 2.0 (Type-A)					
POWER SUPPLY INPUT	Г	24VDC (18÷32VDC) isolated					
DOWED OUDDLY	UPS	UPS with external battery pack (NiMH • 12V/2,5Ah) (backside or separate mounting)	UPS with external battery pack (NiMH • 12V/2,5Ah) (separate mounting)				
POWER SUPPLY (optional)	ATX only S0 version and BM	Kit for ATX mode power supply (push button, internal cable and connector for remote control)	Kit for ATX mode power supply (connector for remote control)				
BATTERY		1x CR2032 Internal access					
O.S. CERTIFIED		Microsoft Windows 10 IoT Enterprise 2019 64 bit					
OPERATING TEMPERA	TURE	0°C ÷ 50°C					
STORAGE TEMPERATU	JRE	-5°C ÷ 60°C					
OPERATING/STORAGE	RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)					
APPROVALS		CE RoHS UKCA cULus Listed					

BM3300



- Intel® Celeron®, Core™ i3, i5, i7 processors of Skylake generation
- RAM up to 16GB
- Built-in UPS with external battery pack (optional)
- Available in RVL version (BM3300 RVL) for the remotation of the DVI-D and USB 2.0 signals up to 100m

















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		BM3300	
PROTECTION GRADE		IP20	
CASE -	Installation	Book mounting	
CASE	Material	Aluminum alloy	
PROCESSOR (soldered on-board)		Intel® Celeron® 3955U 2.00GHz 64bit • 2 cores / 2 threads • 2MB Smart cache • 14nm Intel® Core™ i3-6100U 2.30GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-6300U 2.40GHz (3.00GHz Turbo) 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i7-6600U 2.60GHz (3.40GHz Turbo) 64bit • 2 cores / 4 threads • 4MB Smart cache • 14nm	
CHIPSET		Intel® Skylake U PCH (Platform Controller Hub) • Included into processor chip (Soc)	
VIDEO CONTROLLER		Intel® HD Graphics 510 integrated in Intel® Celeron® processor • 300MHz/900MHz Intel® HD Graphics 520 integrated in Intel® Core™ i3 and i5 processors • 300MHz/1GHz Intel® HD Graphics 520 integrated in Intel® Core™ i7 processor • 300MHz/1,05GHz	
WATCHDOG		Programmable time period	
ТРМ		Intel® PTT (TPM integrated) • Discrete TPM 2.0 module (optional)	
SYSTEM MEMORY RAM		4GB or 8GB or 16GB (1x SODIMM DDR4 module)	
	CFast	1x bootable CFast SATA III slot onboard with external access (up to 240GB)	
MASS STORAGE	SSD mSATA	1x onboard connector for direct insertion of SSD mSATA SATA III	
	SSD/HDD	1x onboard connector for SSD/HDD 2.5" SATA III with internal installation kit	
	LAN	3x Gigabit Ethernet (RJ45)	
INTERFACES	USB	1x USB 3.0 (Type-A) front • 2x USB 3.0 (Type-A)	
	VIDEO	1x DVI-D (Resolution up to 1920x1200) or 1x RJ45 connector for RVL	
ADD-ON INTERFACES (optional)	Position A (max 1)	1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232/422/485 (DB9M) 2x RS232/422/485 optoisolated (DB9M) 2x USB 2.0 (Type-A)	
POWER SUPPLY INPUT		24VDC (18÷32VDC) isolated	
POWER SUPPLY (optional)	UPS	UPS with external battery pack (Pb • 12V/2,5Ah) (separate mounting)	
BATTERY		1x CR2032 Removable front access	
O.S. CERTIFIED		Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit Microsoft Windows 7 Pro/Ultimate 32/64 bit Microsoft Windows Embedded Standard 7E/7P 32/64 bit	
OPERATING TEMPERATURE		$0^{\circ}\text{C} \div 50^{\circ}\text{C}$ $0^{\circ}\text{C} \div 45^{\circ}\text{C} (24\text{x7 HDD or Intel}^{\circ}\text{Core}^{\intercal}\text{i7 processor})$ $5^{\circ}\text{C} \div 45^{\circ}\text{C} (\text{Standard HDD})$	
STORAGE TEMPERATU	IRE	-10°C ÷ 60°C	
OPERATING/STORAGE	RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)	
APPROVALS		CE RoHS UKCA cULus Listed	

PB3400/3600 & BM3400/3600



- Intel® Celeron®, Core™ i3, i5, i7 processors of Skylake and Kaby Lake generation
- RAM up to 32GB
- Built-in UPS with external battery pack (optional)
- Built-in supersapacitors µUPS, with 512kB MRAM for retentive data management (optional)
- PB3400/3600 available in S0, S1 and D2 version, with possibility to install additional interfaces, PCI/PCIe expansion slots and extractable drives slots for 2,5" SSDs/HDDs
- BM3400/3600 available in S0 and S2 versions, with the possibility to install additional interfaces and PCI/PCIe expansion slots, both with predisposition for extractable drawer kit for SSD/HDD: D0 (no kit), D1 (one kit) and D2 (two kits)
- Available with additional RVL (Remote Video Link) interface for remotation of the DVI-D and USB 2.0 signals up to 100m (optional)



CE (ROHS)

GALLERY





PB3400/3600 - (S0 Version)

PB3400/3600 - (S1 Version)



PB3400/3600 - (D2 Version)







COMPARISON TABLE

BM3400/3600 - (S0 Version)

	BM 3400/3600					
	S0			\$2		
	D0	D1	D2	D0	D1	D2
ADD-ON INTERFACES (optional)	✓	✓	✓	✓	✓	✓
EXPANSION SLOTS PCI/PCIe	X	X	X	2	2	2
INTERNAL INSTALLATION KIT for SSDs/HDDs 2,5" SATA III	1	1	1	1, 2	1, 2	1, 2
EXTRACTABLE DRAWER KIT for SSDs/HDDs 2.5" SATA III	X	1	2	X	1	2

PB3400/3600 & BM3400/3600

TECHNICAL DATA

		PB3400/3600	BM3400/3600			
	IP rating	IF	220			
PROTECTION GRADE	NEMA rating		-			
	Installation	Wall mounting	Book mounting			
CASE	Material	Zinc-coated skin pass steel	Aluminum alloy			
PROCESSOR (soldered on-board)	xx3400	Intel® Core™ i3-6100E 2.70GHz 64bit • 2 c Intel® Core™ i5-6440EQ 2.70GHz (3.40GHz Turbo) 6	cores / 2 threads • 2MB Smart cache • 14nm ores / 4 threads • 3MB Smart cache • 14nm 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm			
(soldered on-board)	xx3600	Intel® Core™ i3-7100E 2.90GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-7440EQ 2.90GHz (3.60GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm Intel® Core™ i7-7820EQ 3.00GHz (3.70GHz Turbo) 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm				
	xx3400	Intel® HM170 PCH (Platform Controlle	er Hub) with integrated RAID controller			
CHIPSET	xx3600	Intel® HM175 PCH (Platform Controlle	r Hub) with integrated RAID controller			
CHIPSEI	S2 version with 2x PCle x4	-	Intel® CM236 PCH (Platform Controller Hub) with integrated RAID controller			
xx3400 VIDEO CONTROLLER		Intel® HD Graphics 530 integrated in Int	el® Celeron® processor • 350MHz/950MHz el® Core™ i3 processor • 350MHz/950MHz © Core™ i5 and i7 processors • 350MHz/1GHz			
	xx3600	Intel® HD Graphics 630 integrated in Intel® Core™ i3 processor • 350MHz/950MHz Intel® HD Graphics 630 integrated in Intel® Core™ i5 and i7 processors • 350MHz/1GHz				
WATCHDOG		Programmable time period				
TPM		Intel® PTT (TPM integrated) • Discrete TPM 2.0 module (optional)				
SYSTEM MEMORY RAM		4GB (1x 4GB SODIMM DDR4 module) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module)				
	Cfast	1x bootable CFast SATA III slot onboa	ard with external access (up to 240GB)			
	SSD mSATA	1x onboard connector for direct inserti	on of SSD mSATA SATA III (up to 960 GB)			
MASS STORAGE	SSD/HDD	1x onboard connector for SSD/HDD 2,5" SATA III with internal installation kit	1x or 2x onboard connectors for SSDs/HDDs 2,5" SATA III with internal installation kit (2x not available for S0 version)			
EXTRACTABLE	only D1 version	-	1x extractable SSD/HDD 2,5" SATA III unit			
MASS STORAGE	only D2 version	2x extractable SSDs/	HDDs 2.5" SATA III units			
RAID	only D2 version and BM S2 D0 version	Rai	d 0, 1			
	LAN	4x Gigabit Et	thernet (RJ45)			
INTERFACES	USB	3x USB 3.0 (Type-A) • 2x USB 2.0 (Type-A)	2x USB 3.0 (Type-A) • 2x USB 2.0 (Type-A) • 1x USB 3.0 (Type-A) front			
	SERIAL	1x RS23				
	VIDEO	1x DVI-D (Resoluti	on up to 1920x1080)			
ADD-ON INTERFACES (optional)	Position A (max 1)	1x RS232/422/485 (DB15M)i 2x RS232/42 2x RS232/422/485	5M) + 1x USB 2.0 (Type-A) solated + 1x USB 2.0 (Type-A) 22/485 (DB9M) optoisolated (DB9M) .0 (Type-A)			
	Position B (max 1)	1x or 2x RJ45 connectors for RVL 2x DisplayPort++ V1.2 1x Gigabit Ethernet (RJ45) 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Bluetooth 4.2)¹ and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)¹	1x or 2x RJ45 connectors for RVL (2x not available for S0 D2 version) 2x DisplayPort++ V1.2			

TECHNICAL DATA

		PB3400/3600	BM3400/3600			
EXPANSION SLOTS	only S1 version	1x PCI half-length or 1x PCIe x4 half-length, on riser card, max 5W	-			
EXPANSION SLUTS	only S2 version	-	1x PCIe x4 half-length + 1 x PCI half-length or 2x PCIe x4 half-length, on riser card, max 10W total			
POWER SUPPLY INPU	JT	24VDC (18÷32VDC) isolated				
	UPS	UPS with external battery pack (Pb • 12V/2.5Ah) (backside or separate mounting)	UPS with external battery pack (Pb • 12V/2.5Ah) (separate mounting)			
POWER SUPPLY (optional)	UPS + 512kB MRAM	-	UPS with external battery pack (Pb • 12V/2,5Ah) + 512kB MRAM (separate mounting)			
	μUPS + 512kB MRAM	Supercapacitors μ	IUPS + 512kB MRAM			
	ATX	Kit for ATX mode power supply (push button, internal cable and connector for remote control)	-			
BATTERY		1x CR2032 Internal access	1x CR2032 Removable front access			
0.S. CERTIFIED xx3400		Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit Microsoft Windows 7 Pro/Ultimate 32/64 bit Microsoft Windows Embedded Standard 7E/7P 32/64 bit				
	xx3600	Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit				
OPERATING	without forced ventilation	0°C ÷ 50°C 0°C ÷ 45°C (24x7 HDD or Intel® Core™ i7 processor) 5°C ÷ 45°C (Standard HDD)				
TEMPERATURE	with forced ventilation (only S2 version)	-	0°C ÷ 50°C 0°C ÷ 50°C (24x7 HDD or Core i7 processor) 5°C ÷ 45°C (Standard HDD)			
STORAGE TEMPERAT	TURE	-10°C	÷ 60°C			
OPERATING/STORAG	E RELATIVE HUMIDITY	20% ÷ 90% RH(non-condensing)				
FORCED VENTILATION (optional)		Forced ventilation (2x tachometric fans 40 mm), required to ensure: - operating temperature 0°C ÷ 50°C (24x7 Core i7 processor) - use of expansion cards up to a maximum total				
APPROVALS		CE RoHS UKCA cULus Listed				

^{1.} Wi-Fi and Cellular modules cannot be used if CODESYS SoftPLC control software is installed on the system.

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^{2.} ATEX certification is ensured only without UPS, microUPS, power supply variants, UPS battery kit options and wireless modules
3. MicroUPS+512kB MRAM is not compatible with 2x HDD/SSD option for BM3400/3600 S0 D2

PB3500 & BM3500



- Intel® Celeron®, Core™ i3, i5, i7 processor of Kaby Lake generation
- RAM up to 16GB
- Built-in UPS with external battery pack (optional)
- Built-in supercapacitors μUPS , with 512kB MRAM for retentive data management (optional)
- Available in SL version with reduced depth, S0 version with the possibility to install additional interfaces and S1 version with one PCI or PCIe expansion slot
- Available in RVL version (BM3500 RVL) or with additional RVL (Remote Video Link) interface (PB3500) for the remotation of the DVI-D and USB 2.0 signals up to 100m







PB3500 - (SL Version)

PB3500 - (S0 Version)

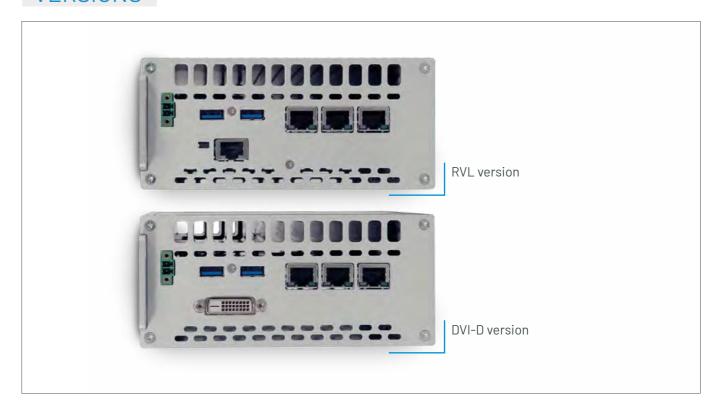




PB3500 - (S1 Version)

BM3500

VERSIONS





CODESYS OPTIONAL

RVL SP OPTIONAL

FANLESS

PB3500 & BM3500

TECHNICAL DATA

		PB3500	BM3500			
	IP rating	IF	220			
PROTECTION GRADE	NEMA rating		-			
	Installation	Wall mounting	Book mounting			
CASE	Material	Zinc coated stainless steel	Aluminum alloy			
PROCESSOR (soldered	on-board)	Intel® Core™ i3-7100U 2.40GHz 64bit • 2 c Intel® Core™ i5-7300U 2.60GHz (3.50GHz Turbo) 6	cores / 2 threads • 2MB Smart cache • 14nm cores / 4 threads • 3MB Smart cache • 14nm 4bit • 2 cores / 4 threads • 3MB Smart cache • 14nm 4bit • 2 cores / 4 threads • 4MB Smart cache • 14nm			
CHIPSET		Intel® Kaby Lake U PCH (Platform Controll	er Hub) • Included into processor chip (SoC)			
VIDEO CONTROLLER		Intel® HD Graphics 620 integrated in Ir Intel® HD Graphics 620 integrated in Int	el® Celeron® processor • 300MHz/900MHz ntel® Core™ i3 processor • 300MHz/1GHz el® Core™ i5 processor • 300MHz/1.10GHz el® Core™ i7 processor • 300MHz/1.15GHz			
WATCHDOG		Programmab	ole time period			
ТРМ	Discrete version only for SO/S1 versions and BM	Intel® PTT (TPM integrated) • Dis	screte TPM 2.0 module (optional)			
SYSTEM MEMORY RAM		4GB or 8GB or 16GB (1x	SODIMM DDR4 module)			
_	Cfast	1x bootable CFast SATA III slot onboa	ard with external access (up to 240GB)			
	SSD mSATA	-	1x onboard connector for direct insertion of SSD mSATA SATA III			
MASS STORAGE	SSD M.2	1x onboard connector for direct insertion of M.2 2280 NVMe PCIe x2 SSD (up to 512GB) or M.2 2280 NVMe PCIe x4 SSD (up to 1TB) ¹ or M.2 2242 SATA III SSD (up to 480GB)	-			
_	SSD/HDD only SO/S1 versions and BM	1x onboard connector for SSD/HDD 2.5" SATA III with internal installation kit				
_	LAN	3x Gigabit Et	thernet (RJ45)			
_	USB	4x USB 3.0 (Type-A)	1x USB 3.0 (Type-A) front • 2x USB 3.0 (Type-A) top			
INTERFACES	SERIAL	1x RS232 (DB9M)	-			
	VIDEO	1x DisplayPort++ V1.2	1x DVI-D (Resolution up to 1920x1200) or 1x RJ45 connector for RVL			
ADD-ON	Position A (max 1)	1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232/422/485 (DB9M) 2x RS232/422/485 optoisolated (DB9M) 2x USB 2.0 (Type-A)				
INTERFACES (optional) not available for SL version	Position B (max 1)	1x Gigabit Ethernet (RJ45) 1x DVI-D (Resolution up to 1900x1200) 1x RJ45 connector for RVL 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/ 5GHz • Bluetooth 4.2) and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)	-			
EXPANSION SLOTS	only S1 version	1x PCI half-length or 1x PCIe x4 half-length, on riser card, max 5W	-			
POWER SUPPLY INPUT		24VDC (18÷32	2VDC) isolated			
	UPS	UPS with external battery pack (Pb • 12V/2.5A) (backside or separate mounting)	UPS with external battery pack (Pb • 12V/2,5Ah) (separate mounting)			
POWER SUPPLY (optional)	UPS + 512kB MRAM	-	UPS with external battery pack (Pb • 12V/2,5Ah) + 512kB MRAM (separate mounting)			
	μUPS + 512kB MRAM	-	Supercapacitors µUPS + 512kB MRAM			
-	ATX only S0/S1 versions	Kit for ATX mode power supply (push button, inter- nal cable and connector for remote control)	-			
	, 23. 0					

TECHNICAL DATA

	PB3500	BM3500					
BATTERY	1x CR2032 internal access	1x CR2032 removable front access					
O.S. CERTIFIED	Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit						
OPERATING TEMPERATURE	0°C ÷ 45°C (24x7 HDD or	÷50°C Intel® Core™ i7 processor) Standard HDD)					
STORAGE TEMPERATURE	-10°C	÷60°C					
OPERATING/STORAGE RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)					
APPROVALS	Ro UI	CE bHS KCA s Listed					

^{1.} The M.2 NVMe PCIe x4 SSDs show actual performance that differs from the manufacturer's claims, as they are driven via 2 lanes (socket M.2 PCIe x2). Data transfer rates are about half of the declared value (comparable to M.2 NVMe PCIe x2 SSDs).

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- Intel® Core™ generation Comet Lake S 35W processors
- Upgradable with RAM up to 32GB
- Expandable with additional interfaces as early as S0 version and integrable with PCIe cards in S2 and S5 versions
- Optimized SSD/HDD management with single or dual removable drawers in D1 and D2 versions
- Guaranteed display up to 100m thanks to RVL interface for remote DVI-D and USB 2.0 signals





















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GALLERY





BM3800 - (S0 Version)

BM3800 - (S2 Version)



BM3800

TECHNICAL DATA

			BM 3800 (35W)					
		S0	S2	S5				
PROTECTION GRADE			IP20					
	Installation		Book mounting					
CASE -	Material		Aluminum alloy					
PROCESSOR (soldered	on-board)	Intel® Core™ i5-10500TE 2.30GHz Intel® Core™ i7-10700TE 2.00GHz	: (3.60GHz Turbo) 64bit • 4 cores / 8 th (3.70GHz Turbo) 64bit • 6 cores / 12 th (4.40GHz Turbo) 64bit • 8 cores / 16 th 4.50GHz Turbo) 64bit • 10 cores / 20 th	reads • 12MB Smart cache • 14nm reads • 16MB Smart cache • 14nm				
CHIPSET		Intel® W480E PCH (Platform Controller Hub) with integrat	ed RAID controller				
VIDEO CONTROLLER		Intel® UHD Graphics 630 in	Intel® UHD Graphics 630 integrated in Intel® Core™ i3 processor • 350MHz/1.1GHz Intel® UHD Graphics 630 integrated in Intel® Core™ i5 and i7 processors • 350MHz/1.15GHz Intel® UHD Graphics 630 integrated in Intel® Core™ i9 processor • 350MHz/1.20GHz					
TPM			Intel® PTT (integrated TPM)					
SYSTEM MEMORY RAM ((soldered)		4GB (1x 4GB SODIMM DDR4 module) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module)					
_	Cfast	1x bootable CFast S	SATA III slot onboard with external acc	cess (up to 240GB)				
MASS STORAGE _	M.2 SSD	1x onboard connector for direct ins	sertion of M.2 2280 NVMe PCIe x4 SSD SSD (up to 480GB)	(up to 512GB) or M.2 2242 SATA III				
	SSD/HDD	1x onboard connectors for SSDs/ HDDs 2,5" SATA III with internal installation kit		rd connectors for SSDs/HDDs 2,5" SATA III with internal installation kit				
EXTRACTABLE MASS S	TORAGE (optional)	1x or 2x extractable SSDs/HDDs 2.5" SATA III units						
RAID			Raid 0, 1					
	LAN	2x Multi-Gig 2.5G Ethernet (RJ45) • 3x Gigabit Ethernet (RJ45)						
INTERFACES	USB	2x USB 3.1 Gen2 (Type-A) • 4x USB 3.1 Gen1 (Type-A) • 1x USB 3.1 Gen1 (Type-A) front						
	VIDEO		1x DisplayPort++ V1.2					
ADD-ON INTERFACES (optional)	Position A (max 1)	1x RS232/ 2	232/422/485 (DB15M) + 1x USB 2.0 (Typ 422/485 (DB15M) isolated + 1x USB 2.0 2x RS232/422/485 (DB9M) x RS232/422/485 optoisolated (DB9M 2x USB 2.0 (Type-A) pabit Ethernet (RJ45) + 1x USB 2.0 (Typ	(Type-A)				
	Position B (max 1)	1x or 2x RJ45 cc	onnectors for RVL (2x not available for 2x DisplayPort++ V1.2	S0 D2 version)				
EXPANSION SLOTS		-	1x PCIe x16 half-length + 1x PCIe x4 half-length or 1xPCIe x4 half-leng- ht + 1x PCIe x1 half-length, on riser card, max 10W total	2x PCIe x8 half-length + 2x PCIe x4 half-length + 1x PCIe x1 half- length, on riser card, max 10W total				
POWER SUPPLY INPUT			24VDC (18÷32VDC) isolated					
POWER SUPPLY	ATX	Kit for ATX m	node power supply (connector for rem	ote control)				
BATTERY			1x CR2032 Removable front access					
O.S. CERTIFIED		Microsoft Windows 10 IoT Enterprise 2021 64 bit						
OPERATING	without forced ventilation	0°C ÷ 50°C 0°C ÷ 45°C (24x7 HDD) 5°C ÷ 45°C (Standard HDD)						
TEMPERATURE	with forced ventilation		0°C ÷ 50°C 0°C ÷ 50°C (24x7 HDD) 5°C ÷ 45°C (Standard HDD)					
STORAGE TEMPERATUR	RE		-20°C ÷ 70°C					
OPERATING/STORAGE I	RELATIVE HUMIDITY		20% ÷ 90% RH(non-condensing)					

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TECHNICAL DATA

		BM 3800 (35W)	
	S0	S2	S5
FORCED VENTILATION (optional)	-	Forced ventilation (2x tachometric fans 40x40x20 mm), required to ensure: - operating temperature 0°C ÷ 50°C (24x7 HDD) - use of expansion cards up to a maximum of 20W total	Forced ventilation (1x tachomet- ric fan 92x92x20 mm), required to ensure: - operating temperature 0°C ÷ 50°C (24x7 HDD) - use of expansion cards up to a maximum of 20W total
APPROVALS		CE RoHS UKCA	

^{1.} The M.2 NVMe PCle x4 SSDs show actual performance that differs from the manufacturer's claims, as they are driven via 2 lanes (socket M.2 PCle x2). Data transfer rates are about half of the declared value (comparable to M.2 NVMe PCle x2 SSDs).

PB5400/5600



- Intel® Celeron®, Core™ i3, i5, i7 processors of Skylake and Kaby Lake generation
- RAM up to 32GB
- · Available in SO version with the possibility to install additional interfaces, S1 version with one PCle expansion slot and S3 version with three PCle expansion slots
- Available with additional RVL interface for remotation of the DVI-D and USB 2.0 signals up to 100m (optional)
- Available with 115/230VAC power supply (optional)

GALLERY



PB5400/5600 - (S0 Version) - 24VDC



PB5400/5600 - (S0 Version) - 230VAC



PB5400/5600 - (S1 Version) - 24VDC



PB5400/5600 - (S1 Version) - 230VAC



PB5400-5600 - (S3 Version) - 24VDC



PB5400-5600 - (S3 Version) - 230VAC

DETAIL - EXTRACTABLE DRIVES SLOT







RVL OPTIONAL



PB5400/5600

TECHNICAL DATA

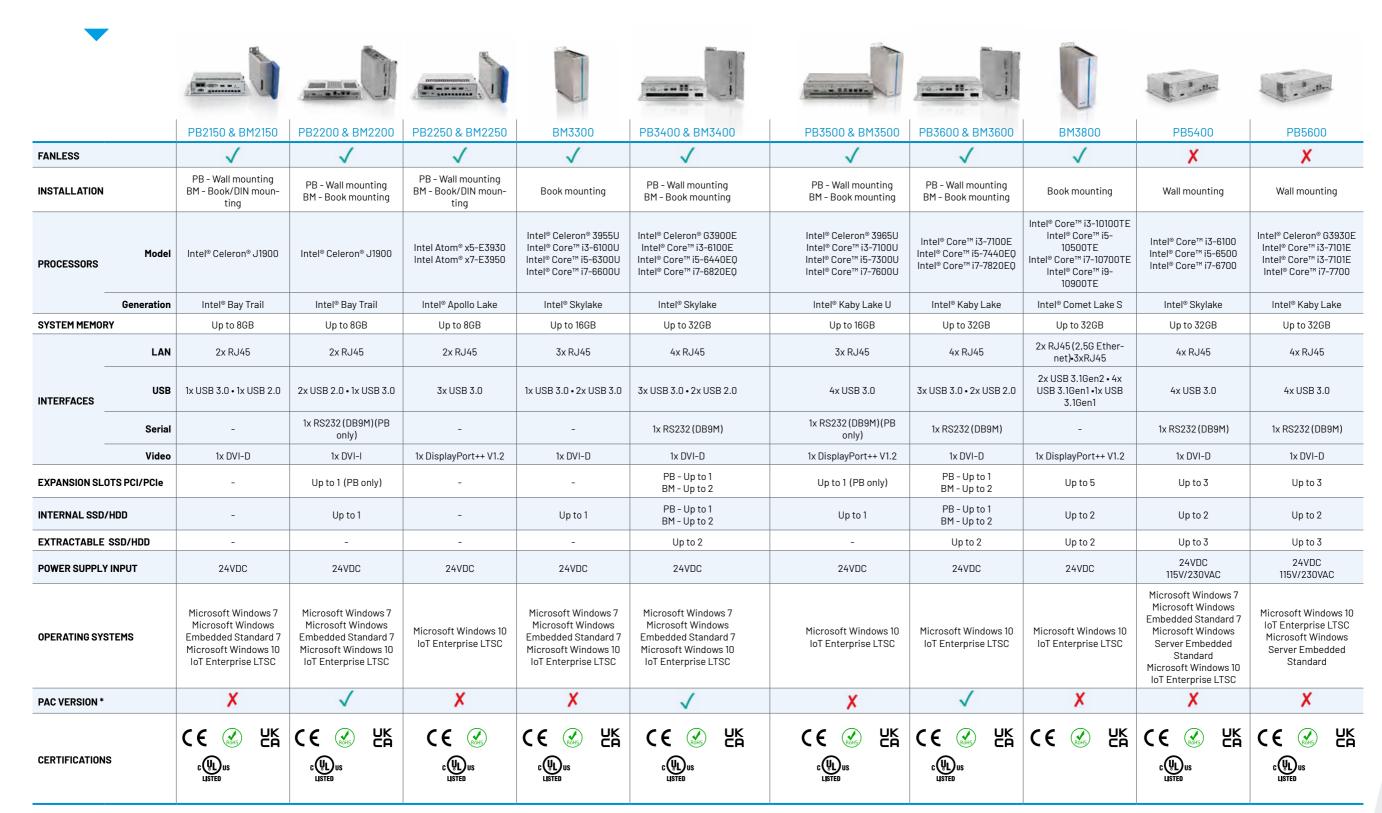
		PB5400/5600
PROTECTION GRADE	IP rating	IP20
PROTECTION GRADE	NEMA rating	-
0405	Installation	Wall mounting
CASE -	Material	Zinc-coated skin pass steel
PROCESSOR -	xx5400	Intel® Core™ i3-6100 3.70GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-6500 3.20GHz (3.60GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm Intel® Core™ i7-6700 3.40GHz (4.00GHz Turbo) 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm
(soldered on-board)	xx5600	Intel® Celeron® G3930E 2.90Ghz 64bit • 2 cores / 2 threads • 2MB Smart cache • 14nm Intel® Core™ i3-7101E 3.90Ghz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-7500 3.40Ghz (3.80GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm Intel® Core™ i7-7700 3.60Ghz (4.20GHz Turbo) 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm
CHIPSET		Intel® C236 PCH (Platform Controller Hub) with integrated RAID controller
	xx5400	Intel® HD Graphics 530 integrated in Intel® Core® i3 and i5 processors • 350MHz/1.05GHz Intel® HD Graphics 530 integrated in Intel® Core® i7 processor • 350MHz/1.15GHz
VIDEO CONTROLLER	xx5600	Intel® HD Graphics 610 integrated in Intel® Celeron® processor • 350MHz/1GHz Intel® HD Graphics 630 integrated in Intel® Core® i3 and i5 processors • 350MHz/1.10GHz Intel® HD Graphics 630 integrated in Intel® Core® i7 processor • 350MHz/1.15GHz
TPM		Intel® PTT (TPM integrated) • Discrete TPM 2.0 module (optional)
SYSTEM MEMORY RAM		4GB (1x 4GB SODIMM DDR4 module) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module)
	CFast	1x bootable CFast SATA III slot onboard with external access (up to 240GB)
1ASS STORAGE	SSD M.2	1x onboard connector for direct insertion of M.2 2280 NVMe PCIe x4 SSD (up to 512GB) or M.2 2242 SATA III SSD (up to 480GB)
_	SSD/HDD	2x onboard connectors for SSDs/HDDs 2.5" SATA III with internal installation kit
EXTRACTABLE	S0/S1/S3 versions	1x extractable SSD/HDD 2.5" SATA III unit
MASS STORAGE	only S1/S3 versions	2x extractable SSDs/HDDs 2.5" SATA III units
RAID		Raid 0, 1
	LAN	4x Gigabit Ethernet (RJ45)
	USB	4x USB 3.0 (Type-A)
INTERFACES	SERIAL	1x RS232 (DB9M)
	VIDEO	1x DVI-D (Resolution up to 1920x1080)
ADD-ON	Position A (max 1)	1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232/422/485 (DB9M) 2x RS232/422/485 optoisolated (DB9M) 2x USB 2.0 (Type-A)
INTERFACES (optional)	Position B (max 1)	1x Gigabit Ethernet (RJ45) 1x or 2x RJ45 connectors for RVL 2x DisplayPort++ V1.2 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Bluetooth 4.2) and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)
	only S1 version	1x PCIe x16 half-length, on riser card, max 75W
EXPANSION SLOTS	only S3 version	1x PCIe x16 half-length + 1xPCIe x4 half-length, on riser card, max 75W 1x PCIe x16 half-length + 1xPCIe x4 half-length + 1xPCIe x1 half-length, on riser card, max 80W 2x PCIe x8 half-length + 1x PCIe x4 half-length, on riser card, max 85W 3x PCI half-lenght, on riser card, max 30W 2x PCI half-lenght + 1x PCIe x4 half-lenght, on riser card, max 35W
POWER SUPPLY		24VDC (18÷32VDC) isolated
INPUT	optional	115V/230VAC (85÷264VAC) isolated, autoranging
POWER SUPPLY (optional)	АТХ	Kit for ATX mode power supply (push button, internal cable and connector for remote control)

TECHNICAL DATA

PB5400/5600						
1x CR2032 Internal access						
Microsoft Windows 7 Pro/Ultimate 64 Microsoft Windows Embedded Standard 7E	oit 7P 64 bit					
0°C ÷ 50°C 0°C ÷ 45°C (24x7 HDD or Intel® Core™ i7 pro 5°C ÷ 45°C (Standard HDD)	cessor)					
-10°C ÷ 60°C						
20% ÷ 90% RH (non-condensing)						
CE RoHS UKCA cULus Listed						
xx560	1x CR2032 Internal access Microsoft Windows 10 IoT Enterprise 2019 I Microsoft Windows 7 Pro/Ultimate 64 b Microsoft Windows Embedded Standard 7E/7 Microsoft Windows Server Embedded Standard 2 xx5600 Microsoft Windows 10 IoT Enterprise 2019 I Microsoft Windows Server Embedded Standard 2 0°C ÷ 50°C 0°C ÷ 45°C (24x7 HDD or Intel® Core™ 17 proc 5°C ÷ 45°C (Standard HDD) -10°C ÷ 60°C 1UMIDITY 20% ÷ 90% RH (non-condensing) CE RoHS UKCA					

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COMPARISON TABLE



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 $^{^{\}ast}$ with UPS + 512kB MRAM for retentive data management and Codesys software



BM1XY FAMILY



- Intel® Atom™ x5, x7 processors of SoC Apollo Lake generation
- Available with 4 ports Gigabit Ethernet switch (only BM121 and BM131)
- Available with Wi-Fi/Bluetooth interfaces and 4G Global modem (only BM122, BM130 and BM131)
- DIN rail mounting available
- Wall mounting available (only BM100)
- Built-in UPS with external battery pack (optional)

VERSIONS







BM100

BM110

BM120







BM121

BM122

BM130



BM131



FANLESS





BM1XY FAMILY

TECHNICAL DATA

		BM100	BM110	BM120	BM121	BM122	BM130	BM131		
PROTECTION GRADE	IP rating				IP20					
	Installation	Book / DIN rail / Wall Mounting			Book / DIN	rail Mounting	rail Mounting			
CASE	Material			Ano	dized aluminur	n alloy				
	Dimensions (w/o mounting)	100x100x- 39,4mm	100x100x- 58,4mm	10	10x100x79mm		100x100x	100mm		
PROCESSOR (soldered	l on-board)			E3930 1.3GHz (1.8 GI E3950 1.6GHz (2.0 G						
CHIPSET				Intel® Apollo Lake	• Included into	processor chip	(SoC)			
VIDEO CONTROLLER				cs 500 integrated in cs 505 integrated in						
ТРМ				Intel®	PTT (TPM inte	grated)				
SYSTEM MEMORY	with x5-E3930			4GB SC	DDIMM LP-DDR	4 module				
RAM (soldered)	with x7-E3950			4GB or 8GI	B SODIMM LP-0	DR4 module				
MASS STORAGE	SSD M.2		1x onboard c	onnector for direct	insertion of M	.2 2242 SATA III	SSD (up to 480GB)			
	LAN	2x Gigabit (RJ	t Ethernet 145)	4x Gigabit Ethernet (RJ45)	2x Gigabit Et	hernet (RJ45)	4x Gigabit Ethernet (RJ45)	2x Gigabit Ethernet (RJ45)		
	LAN Switch		-		1x Unman- aged Giga- bit Switch (4x RJ45)		-	1x Unman- aged Gigabit Switch (4x RJ45)		
INTERFACES	USB	2x USB 3.0 (Type-A)		4x USB 3.0 (Туре-А)	2x USB 3.0 (Type-A)	AVIIGE (II			
	SERIAL	-		1x RS232/422/485 (DB9M)		-	1x RS232/422/485 (DB9M)	-		
	VIDEO			1x	DisplayPort++	V1.2				
	DIGITAL INPUT	-		2x I	Digital Input (0-	÷24V isolation 500V)				
	DIGITAL OUTPUT	-		2x Dig	gital Output (N.	0. max 200mA	24VDC)			
	Model			-		Bointec	DPE109A (mPCle i	nterface)		
	Standard			-		IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Blue- tooth 4.2				
	Security			-		WEP 64/12	8bit, WPA, WPA2,	WPS, 802,1x		
Wi-Fi Module	RF Output Power			-		2.4GF 5GH:	2.4GHz (802.11b): 18 dBm ± 2dB 2.4GHz (802.11n): 14 dBm ± 2dB 5GHz (802.11a): 13 dBm ± 2dB 5GHz (802.11ac): 10 dBm ± 2dB			
	RF sensitivity			-	-		11a, 20MHz:- MCS=0 PER @ -90 dBm, typical 11n, 20MHz:- MCS=0 PER @ -90 dBm, typical 11b, 20MHz@8%PER:- 11Mbps PER @ -91 dBm, typical <0,1% BER at -70dBm (Bluetooth)			
	Feature			-		Client	mode / Access poir	nt mode		
	Antenna			=		2x RF	P-SMA Female conf	nector		

TECHNICAL DATA

		BM100	BM110	BM120	BM121	BM122	BM130	BM131		
	Model			-		SIMCom S	IM7600G-H (mPCle	interface)		
Cellulare Module	Frequency Bands			-		FDD-LTE: B1/B2/B3/B4/B5/B7/B8/B12/B13/ B18/B19/B20/B25/B26/B28/B66 TDD-LTE: B38/B39/B40/B41 UMTS/HSDPA/HSPA+: B1/B2/B4/B5/B6/B8/ B19 GSM/GPRS/EDGE: B2/B3/B5/B8				
	Data Transfer			-		up to 150Mbp	os (Downlaod) / 50N	1bps (Upload)		
	SIM			-		1x Micro SIN	M card socket, pusl	n-push type		
	Antenna			-		2x S	SMA Female conne	ctor		
POWER SUPPLY INPUT	Г			24V[DC (18÷32VDC) is	solated				
POWER SUPPLY (optional)	UPS	-		UPS with		ry pack (NiMH • mounting)	12V/2,5Ah)			
BATTERY				1x CI	R2032 Internal	access				
O.S. CERTIFIED				Microsoft Wind	lows 10 IoT Ente	erprise 2019 64	bit			
OPERATING	with x5-E3930	0°C ÷ 55°C			0°C -	÷ 50°C				
TEMPERATURE	with x7-E3950				0°C ÷ 50°C					
STORAGE TEMPERATU	JRE				-10°C ÷ 60°C					
OPERATING/STORAGE	RELATIVE HUMIDITY			20% ÷ 9	00% RH (non-co	(non-condensing)				
APPROVALS					CE RoHS UKCA cULus Listed					

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PANEL

COMPARISON TABLE

















		1		10 0 11	10.1			4 4 4
		BM100	BM110	BM120	BM121	BM122	BM130	BM131
INSTALLATION	I	Book/ DIN rail/ Wall mounting	Book/ DIN rail mounting	Book/ DIN rail mounting	Book/ DIN rail mounting Book/ DIN rail mounting		Book/ DIN rail mounting	Book/ DIN rail mounting
PROCESSORS	Model	Intel Atom® x5-E3930 Intel Atom® x7-E3950	Intel Atom® x5-E3930 Intel Atom® x7-E3950	Intel Atom® x5-E3930 Intel Atom® x7-E3950	Intel Atom® x5-E3930 Intel Atom® x7-E3950			
	Generation	Intel® Apollo Lake	Intel® Apollo Lake	Intel® Apollo Lake	Intel® Apollo Lake	Intel® Apollo Lake	Intel® Apollo Lake	Intel® Apollo Lake
SYSTEM MEMO	RY	Up to 8GB	Up to 8GB	Up to 8GB	Up to 8GB	Up to 8GB	Up to 8GB	Up to 8GB
	LAN	2x RJ45	2x RJ45	4x RJ45	2x RJ45	2x RJ45	4x RJ45	2x RJ45
	LAN switch	-	-	-	1x Unmanaged Gigabit Switch (4x RJ45)	-	-	1x Unmanaged Gigabit Switch (4x RJ45)
	USB	2x USB 3.0	2x USB 3.0	4x USB 3.0	4x USB 3.0	2x USB 3.0	4x USB 3.0	4x USB 3.0
	Serial	-	-	1x RS232/422/485 (DB9M)	-	-	1x RS232/422/485 (DB9M)	-
INTERFACES	Video	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2
	Digital input	-	2	2	2	2	2	2
	Digital output	-	2	2	2	2	2	2
	Wi-Fi module	X	X	X	X	✓	✓	✓
	Cellular module	X	X	X	X	✓	✓	✓
POWER SUPPLY	Y INPUT	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC
OPERATING SY	STEMS	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC			
		CE SHE CA	CE SUK CA	CE & UK	CE & UK	CE & CA	CE SUK	CE S UK
CERTIFICATION	NS	C UL US LISTED	C UL US Listed	C Us US	C ULSTED	C UL US LISTED	C UL US	C ULSTED



VK3500 SERIES



- VESA 75/100 or top/bottom arm mounting
- Available in landscape and portrait version
- Powder coated die-cast aluminum chassis with anti-scratch treatment
- 15.6", 18.5", 21.5" and 24" TFT LCDs in Wide aspect ratio for landscape version (VK3500 and VK3500-BA)
- 21,5" and 24" TFT LCDs in Wide aspect ratio for portrait version (VK3500P-BA)
- Front panels with minimized aluminum (ALU) and glass True Flat (TFM) frame with multitouch projected capacitive touchscreen (only landscape version)
- Front panels with minimized aluminum and glass True Flat (TFM) frame with multitouch projected capacitive touchscreen
- Full IP65 protection grade
- Available with configurable Button Area for the installation of Ø22 hard-wired elements (VK3500-BA and VK3500P-BA)
- Celeron®, Core™ processors of Kaby Lake generation
- Available with RVL technology for the remotation of the DVI-D and USB 2.0 signals up to 100m (optional)





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TECHNICAL DATA

		VK3500-BA-ALU	VK3500-BA-TFM	VK3500-ALU	VK3500-TFM	VK3500P-BA-TFM			
LED BACKLIGHT TFT LC	D		15.6" W - 15.6" W - 1 18.5" W - 18.5" W - 1 21.5" W - 1 24"W - 19	920x1080 1366x768 920x1080 920x1080		21.5" W - 1920×1080 24"W - 1920×1080			
ORIENTATION			Lands	scape		Portrait			
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch	Resistive 5 wires	P-CAP Multitouch	P-CAP Multitouch			
FRONT PANEL	Material	Aluminum	True Flat Aluminum	Aluminum	True Flat Aluminum	True Flat Aluminum			
	IP rating			Full IP65					
PROTECTION GRADE —	NEMA rating	UL Type 1, 4)	x (indoor only)	UL Type 1, 4x (in	door only) and 12	UL Type 1, 4x (indoor only)			
	Installation	VESA 75/100 or po		nounting system con HASEKE ULT KUPPL		CP40/ROLEC TARAPLUS/			
CASE	Material			Aluminum alloy AN A	.B46400				
UAGE _	Color			-scratchable painted					
_	Accesories			· · · · · · · · · · · · · · · · · · ·	keyboard holder kit				
BUTTON AREA (optional	1)	See dedica	ated section		-	See dedicated section			
PROCESSOR (soldered o	on-board)	Intel® C Intel® Core™ i5-	•	Hz • 64bit • 2 cores / GHz Turbo) • 64bit • 2	4 threads • 3MB Sma 2 cores / 4 threads • 3				
CHIPSET		Intel® Kaby Lal	ke PCH-LP (Platform	Controller Hub - Low	Power) • Included int	o processor chip (SoC)			
VIDEO CONTROLLER		Int Int	Intel® HD Graphics 610 el® HD Graphics 620 i el® HD Graphics 620 tel® HD Graphics 620 Dire	ntegrated in Core™ i integrated in Core™ i	3 processors • 300Ml 5 processors • 300Ml i7 processor • 300Ml	Hz/1.00GHz Hz/1.10GHz			
WATCHDOG				Programmable time	period				
TPM				Intel® PTT (TPM inte	Intel® PTT (TPM integrated)				
SYSTEM MEMORY RAM		4GB or 8GB or 16GB (1 x SODIMM DDR4 module)							
	CFast	1x bootable CFast SATA III slot onboard with external access (up to 240GB)							
MASS STORAGE	M.2 SSD	1	x onboard connector or M.2	for direct insertion of 2280 NVMe PCIe x4 S		le x2 SSD			
_	LAN			3x Gigabit Ethernet	(RJ45)				
INTERFACES	USB		3x USB 3.0 (Type-A	a) • 1x USB 3.0 (Type-	A) rear with protection	n cap			
	VIDEO (optional)		1x DisplayP	ort++ V1.2 or 1x RJ45	connector for RVL				
ADD-ON INTERFACES (optional)	Position A (max 1)		1 x F	1x RS232/422/485 (RS232/422/485 (DB1) 1x Gigabit Ethernet	5M) isolated				
CONNECTIVITY (optional	ni)		1x Wi-Fi module (IEE	E 802.11 a/b/g/n/ac,	2.4GHz/5GHz • Blueto	ooth 5.1)			
POWER SUPPLY INPUT				24VDC (18÷32VDC) i	solated				
POWER SUPPLY (option	al) ATX	TX Kit for ATX mode power supply (internal cable and push button on button area)							
BATTERY		1x CR2032 Removable front access							
O.S. CERTIFIED	erprise 2019 64bit								
OPERATING TEMPERATI	JRE		0°C ÷ 50°C						
STORAGE TEMPERATUR	E			-10°C ÷ 60°C					
OPERATING/STORAGE R	RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)							
APPROVALS		CE RoHS UKCA cULus Listed							

^{1.} The M.2 NVMe PCle x4 SSDs show actual performance that differs from the manufacturer's claims, as they are driven via 2 lanes (socket M.2 PCle x2). Data transfer rates are about half of the declared value (comparable to M.2 NVMe PCle x2 SSDs).

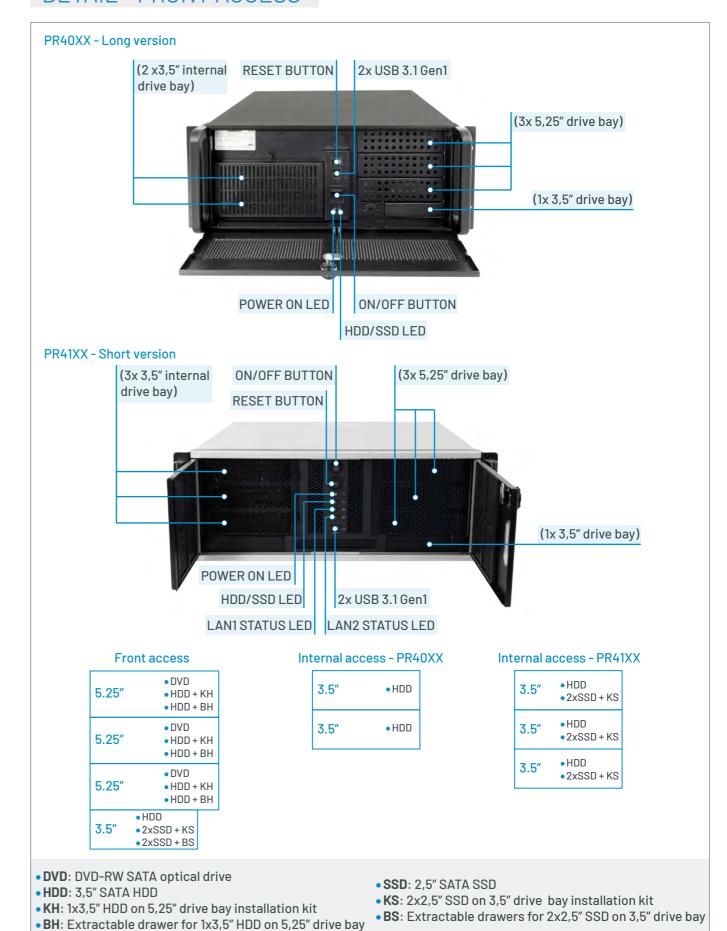
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PR4XXX SERIES



- Available in long (PR40XX) and short versions (PR41XX)
- 24/7 operation
- High processing capacity
- High reliability
- Multiplicity of use
- Intel® Core™ i3, i5, i7 processors of Skylake, Kaby Lake and Coffee Lake generation

DETAIL - FRONT ACCESS



PR4XXX SERIES

TECHNICAL DATA

		PR4048	PR4148	PR4049	PR4149	PR4050	PR4150	PR4051	PR4151				
					Cabinet rack	mount 19" 4U	unt 19" 4U						
	ASEM Logo				Adhesi	ve label							
CASE	Material	Electro galvanized Steel	Hot dip galvanized Steel	Electro galvanized Steel	Hot dip galvanized Steel	Electro galvanized Steel	Hot dip galvanized Steel	Electro galvanized Steel	Hot dip galvanized Steel				
CABINET FORMAT		Long	Short	Long	Short	Long	Short	Long	Short				
MOTHERBOARD		А	TX format, D3	446-S2 (Fujits	u)	1	ATX format, D3	3646-S (Fujitsu)				
PROCESSOR (soldered on	-board)	3.70GHz 64 / 4 threads cache • 14r LGA Intel® Core 2.70GHz (3.3 64bit • 4 core • 3MB Smart • Socket Intel® Core 3.40GHz (4.0 64bit • 4 core	• 3MB Smart Im • Socket 11151 2 [™] i5-6400 .0GHz Turbo) 2s / 4 threads cache • 14nm LGA1151 2 [™] i7-6700 .0GHz Turbo) 2s / 8 threads art Cache •	3.40GHz (3.8 64bit • 4 core • 6MB Smart • Socket Intel® Core 3.60GHz (4.2 64bit • 4 core • 8MB Smart	e™ i5-7500 i0GHz Turbo) i0GHz Turbo) i0GHz Turbo) i0GHz 1151 e™ i7-7700 i0GHz Turbo) i0GHz Turbo) i0GHz Turbo i0GHz Turbo i0GHz Turbo i0GHz Turbo i0GHz Turbo i0GHz Turbo i0GHz Turbo	*Socket LGAII Intel® Core™ i7-8700 3.20GHz (4.60GHz Turbo) 6.46bit • 6 cores / 12 threads 1.4nm • Socket LGAII51 Intel® Core™ i7-8700 3.20GHz (4.60GHz Turbo) 6.4bit • 6 cores / 12 threads • 12MB Smart cache 1.4nm • Socket LGAII51 Intel® Xeon™ E-2176G 3.70GHz (4.70GHz Turbo) 64bit • 6 cores / 12 threads • 12MB Smart cache 1.4nm • Socket LGAII51			OGHz Turbo) es / 4 threads cache • 14nm LGA1151 ™ i5-9400E OGHz Turbo) es / 6 threads cache • 14nm LGA1151 ™ i7-9700E OGHz Turbo) es / 8 threads art cache •				
CHIPSET		Intel® C236 Express Chipset with integrated RAID controller			Intel® C246 Express Chipset with integrated RAID controller								
VIDEO CONTROLLER		integrated I i3 processor 050 Intel® HD 530 integr Core™ i5 p 350MHz Intel® HD G integrated I i7 processor 150 Multi Displa	GHz Graphics ated Intel® processor • /950MHz raphics 530 ntel® Core™ • 350MHz/1.	integrated I i5 processor 100 Intel® HD G integrated I i7 processor 150 Multi Displa	• 350MHz/1. GHz raphics 630 ntel® Core™	Intel® UHD Graphics 630 integrated Intel® Core™ i3 processor • 350MHz/1. 10GHz Intel® UHD Graphics 630 integrated Intel® Core™ i5 processor • 350MHz/1. 05GHz Intel® UHD Graphics 630 integrated Intel® Core™ integrated Intel® i5 processor • 350MHz/1. 20GHz Intel® UHD Graphics 630 integrated Intel® Core™ i7 processor • 350MHz/1. 20GHz Intel® UHD Graphics G30 integrated Intel® i5 processor • 350MHz/1. Intel® UHD Graphics G30 integrated Intel®		ntel® Core™ • 350MHz/1. 6Hz 6raphics 630 ntel® Core™ • 350MHz/1. 6Hz 6raphics 630 ntel® Core™ • 350MHz/1. 6Hz 6raphics 630 ntel® Core™ • 350MHz/1. 6Hz y supported					
GRAPHICS LIBRARY		Dir	extX 12 • Open	GL 4.4 suppor	ted	Dir	extX 12 • Open	GL 4.5 support	ted				
AUDIO		Realtek® A		nnel High Defir DEC	ition Audio	Realtek® Al		nnel High Defin DEC	ition Audio				
ETHERNET CONTROLLER				9LM with supp d Magic Packet		Intel® I210AT and Intel® I219LM with support of Intel® AMT 11, WoL and Magic Packet™							
ТРМ				Dis	crete TPM 2.0) module (optional)							
SYSTEM MEMORY RAM				8GE 16GI 32GI	8 (2x 4GB SODI 8 (2x 8GB SOD 8 (2x 16GB SOD	DIMM DDR4 module) DIMM DDR4 module) IDIMM DDR4 module) DDIMM DDR4 module) DDIMM DDR4 module) DDIMM DDR4 module)							
_	M.2 SSD			-		1x onboard c		lirect insertion SD (up to 1TB)	of M.2 2280				
MASS STORAGE	SSD mSATA			or direct insert II (up to 960GB				-					
	SSD/HDD			6x SATA 60	b/s ports for S	SSD 2,5"/HDD 3	3,5" SATA III						

TECHNICAL DATA

		PR4048	PR4148	PR4049	PR4149	PR4050	PR4150	PR4051	PR4151	
RAID			Raid 0, 1, 5, 10 ¹							
DDIVE DAY	External					r (h=1,65") (H=1,00")				
DRIVE BAY	Internal	2x 3,5" (H=1,00")	3x 3,5" (H=1,00")	2x 3,5" (H=1,00")	3x 3,5" (H=1,00")	2x 3,5" (H=1,00")	3x 3,5" (H=1,00")	2x 3,5" (H=1,00")	3x 3,5" (H=1,00")	
	LAN		2x Gigabit Ethernet (RJ45)							
	USB	2x U	SB 3.1 Gen1(Ty 2x USB 2.0 inte	A) • 4x USB 2.0 /pe-A) front ac ernal connecto (Type-A) interi	cess r	2x USB 3.1 Gen2 (Type-A) • 2x USB 3.1 Gen1 (Type-A) • 4x USB 2.0 (Type-A) 2x USB 3.1 Gen1 (Type-A) front access 2x USB 2.0 internal connector 1x USB 3.1 Gen2 Stick (Type-A) internal				
INTERFACES	SERIAL		1x RS23	2 (DB9M)				2 (DB9M) rnal connector		
	PERIPHERAL DEVICES		1	x PS/2 Keyboa	rd port (purple	e) • 1x PS/2 mou	ıse port (greei	n)		
	VIDEO				1x DVI-D • 2x D	isplayPort V1.2	!			
	AUDI0			1x Li	ne In • 1x Line (Out • 1x Micropl	hone			
INTERFACES w/ SLOT	BRACKET		1x RS232 (DB9M) rear				-		
EXPANSION SLOTS		2x PCI full size (32 bit, 33MHz, Rev 2.3) 1x PCle x16 (16 Lanes, Gen3) • 1x PCle x16 (4 Lanes, Gen3) 1x PCle x8 (1 Lane, Gen3) 1x PCle x4 (4 Lanes, Gen3) • 1x PCle x4 (1 Lane, Gen3)				2x PCI full size (32 bit, 33MHz, Rev 2.3) 1x PCIe x16 (16 Lanes, Gen3) • 1x PCIe x16 (4 Lanes, Gen3) 2x PCIe x8 (1 Lane, Gen3) 1x PCIe x1 (Gen3)				
POWER SUPPLY		Inpute voltage 110/230VAC • 400W or 650W, au- toranging Inpute voltage 110/230VAC • 2x 500W, auto- ranging, redundant	Inpute voltage 110/230VAC • 400W or 650W, au- toranging	Inpute voltage 110/230VAC • 400W or 650W, au- toranging Inpute voltage 110/230VAC • 2x 500W, auto- ranging, redundant	Inpute voltage 110/230VAC • 400W or 650W, au- toranging	Inpute voltage 110/230VAC • 400W or 650W, autoranging Inpute voltage 110/230VAC • 2x 500W, autoranging, redundant	Inpute voltage 110/230VAC • 400W or 650W, au- toranging	Inpute voltage 110/230VAC • 400W or 650W, au- toranging Inpute voltage 110/230VAC • 2x 500W, auto- ranging, redundant	Inpute voltage 110/230VAC • 400W or 650W, au- toranging	
O.S. CERTIFIED	IoT Enterpri 64 Microsoft Wi Ultimate Microsoft W bedded Sta	Windows 10 se 2019/2016 bit ndows 7 Pro/ 32/64 bit Vindows Em- ndard 7E/7P 4 bit	Windows Se ded Standa	se 2019/2016 bit			oT Enterprise 2 ed Standard 20			
SPECIAL FEATURES					24/7 op	eration				
OPERATING TEMPERA	ATURE	0°- 40°C with 24x7 HDD 5°- 40°C with standard HDD								
STORAGE TEMPERATI	URE	-10°C ÷ 60°								
OPERATING/STORAGE RELATIVE HUMIDITY	Ξ			2	0 ÷ 90% RH (n	on-condensing	j)			
APPROVALS						E HS				

For RAID 0, 1 configurations at least 2x HDDs 3,5" or 2x SSDs 2,5" are required For RAID 5 configuration a minimum of 3x HDDs 3,5" (no SSDs) are required For RAID 10 configuration, 4x HDDs 3,5" (no SSDs) are required.

MQ200 & MH200



- TFT LCDs in 12.1" and 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio, 12.1", 15.6", 18.5", 21.5" and 24" in Wide aspect ratio
- Aluminum (ALU) e aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat front panels with multitouch projected capacitive touchscreen (TFM)
- Stainless steel True Flat (TFK) front panels with resistive touchscreen
- Front IP65 protection grade
- Video input: 1x DVI-D and 1x DisplayPort
- ATEX certification for QT-TFM version (optional)
- Available in RVL version (MQR200 & MHR200) for the remotation of the DVI-D and USB 2.0 signals up to 100m
- Available with 110/230VAC power supply



*only TFM frontal

TECHNICAL DATA

		MQ200-ALU	MQ200-TFK	MQ200-TFM	MH200-ALU	MH200-TF
LED backlight TFT LCD		12.1" W - 1280×800 15.6" W - 1366×768 15.6" W - 1920×1080 18.5" W - 1366×768 18.5" W - 1920×1080 21.5" W - 1920×1080 24" W - 1920×1080		12.1" - 800×600 12.1" - 1024×768 15" - 1024×768 17" - 1280×1024 19" - 1280×1024		
CUT-OUT			QТ		НТ	
TOUCHSCREEN		Resistiv	e 5 wires	P-CAP Multitouch	Resistive 5 wires	
FRONT PANEL		Aluminum	True Flat Stainless Steel	True Flat Aluminum	Aluminum	True Flat Aluminum
FRONT USB			_		1x USB 2.0 (Typ	e-A), protected
_	IP rating	IP65 - frontal	IP69K - frontal		IP65 - frontal	
PROTECTION GRADE	NEMA rating	UL Type 1, 4x (indoor only)	UL Type 1, 4x (in- door only) and 12	UL Type 1, 4x (indoor only)	UL Type 1, 4x (in	door only) and 12
CASE -	Installation	Panel mounting				
Mat		Zinc-coated skin pass steel				
VIDEO INPUT	MQ/MH	1x DisplayPort 1x DVI-D				
MQR/MHR		1x RJ45 connector for remotation of DVI-D1				
USB INPUT -	MQ/MH	1x USB 2.0 HUB input (Type-B)				
002 01	MQR/MHR	1x RJ45 connector for remotation of U			of USB 2.01	
USB OUTPUT		3x USB 2.0 (Type-A)				
	Optional			1x USB 2.0 (Type-A)		
POWER SUPPLY INPUT		24VDC (18÷32VDC) isolated				
		110V/230VAC (90÷264VAC) isolated, autoranging				
OPERATING TEMPERATURE		0° ÷ +50°C				
STORAGE TEMPERATURE		-5° ÷ +60°C				
OPERATION/STORAGE RELATIVE HUMIDITY		20% ÷ 90% RH (non-conder		nsing)		
APPROVALS		Ro Uk	CE IHS ICA Listed	CE RoHS UKCA cULus Listed ATEX zone 2/22	Ro Uk	EE IHS ICA Listed

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^{1.} The same RJ45 connector is used for remotation of DVI-D and USB 2.0 signals

MK200 SERIES



- Available in landscape and portrait version
- Powder coated die-cast aluminum chassis with anti-scratch treatment
- 15.6", 18.5", 21.5" and 24" TFT LCDs in Wide aspect ratio for landscape version (MK200-TFM and MK200-BA-TFM)
- 21,5" and 24" TFT LCDs in Wide aspect ratio for portrait version (MK200P-BA-TFM)
- Resolution up to Full HD
- New front panels with minimized aluminum and glass True Flat frame with multitouch projected capacitive touchscreen
- Full IP65 protection grade
- Video input: 1x DVI-D and 1x DisplayPort
- Available with configurable Button Area for the installation of Ø22 hard-wired elements (MK200-BA-TFM and MK200P-BA-TFM)
- Available in RVL version (MKR version) for the remotation of the DVI-D and USB 2.0 signals up to 100m





ACCESSORI

PAG. 126





TECHNICAL DATA

		MK200-BA-ALU	MK200-BA-TFM	MK200-ALU	MK200-TFM	MK200P-BA-TFM
LED BACKLIGHT TFT LCD		15.6" W - 1366x768 15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24" W - 1920x1080			21.5" W - 1920x1080 24" W - 1920x1080	
ORIENTATION			Landso	cape		
TOUCHSCREEN		Resistive 5 wires	P-CAP multitouch	Resistive 5 wires	P-CAP multitouch	P-CAP multitouch
FRONT PANEL		Aluminum	True Flat Aluminum	Aluminum	True Flat Aluminum	True Flat Aluminum
	IP rating			Full IP65		
PROTECTION GRADE	NEMA rating	UL Type 1, 4x (indoor only)		UL Type 1, 4x (i	ndoor only) and 12	UL Type 1, 4x (indoor only)
Installation		VESA 75/100 or pole/suspension arm mounting system compatible with RITTAL CP40/ROLEC TARAPLUS/ HASEKE ULT KUPPLUNG 48				
CASE	Material					
	Colour	Anti-scratchable painted - RAL 9006				
	Accessories	Side handles, perimetral handle, keyboard holder kit				
BUTTON AREA (optional)		See dedicated section -		See dedicated section		
VIDEO INPUT		1x DisplayPort 1x DVI-D				
	Remote version MKR	1x RJ45 connector for remotation of DVI-D1				
USB INPUT		1x USB 2.0 HUB input (Type-B)				
USB INPUT	Remote version MKR		1x RJ45 cor	nnector for remotat	on of USB 2.01	
UCD OUTDUT				3x USB 2.0 (Type-	۵)	
USB OUTPUT	Rear access 1x USB 2.0 (Type-A) with protection cap					
POWER SUPPLY INPUT		24VDC (18÷32VDC) isolated				
OPERATING TEMPERATURE		0° ÷ +50°C				
STORAGE TEMPERATURE		-5° ÷ +60°C				
OPERATION/STORAGE RELATIVE HUMIDITY		20% ÷ 90% RH (non-condensing)				
APPROVALS		CE RoHS UKCA cULus Listed				

^{1.} The same RJ45 connector is used for remotation of DVI-D and USB 2.0 signals

MX200



- Stainless steel (AISI 304L) chassis with sloping surfaces to avoid dust accumulation
- Stainless steel (AISI 304L) hygienic screws with under-head gasket
- Fully cleanable blue silicone gaskets
- 18.5" TFT LCDs in Wide aspect ratio
- Resolution up to Full HD
- Stainless steel (AISI 304L) True Flat front panels with resistive touchscreen
- Top/bottom arm mounting
- Up to full IP69K protection grade
- Video input: 1x DVI-D and 1x DisplayPort
- Available with configurable Button Area for the installation of hard-wired elements: Ø22 cleanable silicon elements, or Ø30 low profile stainless steel elements
- Available in RVL version (MXR200) for the remotation of the DVI-D and USB 2.0 signals up to 100m







TECHNICAL DATA

BUTTON AREA

CE WHS CA

	I		1	I	I	
		MX200-TFK	MX200-TFMK	MX200-BA-TFK	MX200-BA-TFMK	
LED BACKLIGHT TFT LCD		18.5" W - 1366x768 18.5" W - 1920x1080				
TOUCHSCREEN		Resistive 5 Wires	P-CAP Multitouch	Resistive 5 Wires	P-CAP Multitouch	
FRONT PANEL			True Flat S	tainless Steel		
PROTECTION GRAD	E	Full IP69K		Full IP65		
BUTTON AREA			-	See dedica	ated section	
		6x M5 screws	•	ng to build your own fixing fla	ange (included)	
CASE	Installation	or Top/bottom arm mounting with customized flange for Ø48mm tubes (optional)				
	Material	Stainless Steel AISI 304L				
VIDEO INPUT		1x DisplayPort 1x DVI-D				
	Remote version MXR		1x RJ45 connector f	or remotation of DVI-D¹		
USB INPUT		1x USB 2.0 HUB input (Type-B)				
USB INPU I	Remote version MXR	1x RJ45 connector for remotation of USB 2.01				
USB OUTPUT			3x USB 2.0 (Type-A)			
028 00 1501	Optional	2x USB 2.0 (Type-A) rear access with protection cap				
POWER SUPPLY INPUT		24VDC (18÷32VDC) isolated				
OPERATING TEMPERATURE		0° ÷ +50°C				
STORAGE TEMPERATURE		-5° ÷ +60°C				
OPERATION/STORAGE RELATIVE HUMIDITY		20% ÷ 90% RH (non-condensing)				
APPROVALS		CE RoHS UKCA cULus Listed				

1. The same RJ45 connector is used for remotation of DVI-D and USB 2.0 signals

COMPARISON TABLE









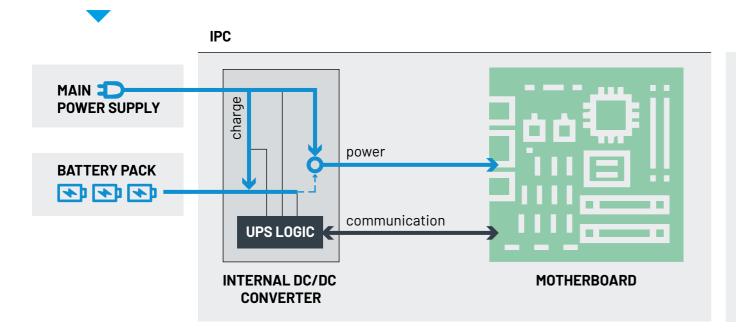
		MK200	MX200	MQ200 & MH200
	Wide sizes	15,6", 18,5", 21,5" and 24"	18,5"	12,1", 15,6", 18,5", 21,5" and 24"
FRONT	Narrow sizes	-	-	12,1", 15", 17", 19"
PANELS	Types	ALU	TFK	ALU, TF, TFM, TFK
	Touchscreen technology	Multitouch	Resistive	Resistive Multitouch
PROTECTION	GRADE	Up to Full IP65	Up to Full IP69K	Up to Full IP69K
CASE MATERIAL		Aluminum alloy AN AB46400	Stainless Steel AISI 304L	Zinc-coated skin pass steel
INSTALLATION		VESA 75/100 or pole/suspension arm mounting	Top/bottom arm mounting with custo- mized flange	Panel mounting
ACCESSORIES (optional)		Side handles Perimetral handle Keyboard holder kit	-	-
BUTTON AREA (optional)		✓	✓	Х
POWER SUPPLY INPUT		24VDC	24VDC	24VDC 110V/230VAC
CERTIFICATIO	NS	CE UK CA	CE SUS UK CH CULUS US	CE SUK CH CH CLISTED

^{*} only for QT-TFM





INTEGRATED UPS



ASEM has developed an integrated UPS (Uninterruptable Power Supply) system for its IPCs to prevent sudden shutdowns with consequent data loss or damage due to unexpected primary power supply failures. The control electronics are integrated into the power supply module to ensure maximum reliability and noise immunity to maintain the IPC and UPS communication interfaces within the system.

The control logic, organised on several levels, is entirely designed and developed by the ASEM R&D Team and includes:

- a hardware section capable of switching the power source of the primary voltage to the battery and vice versa in just microseconds
- a configurable hardware section for monitoring battery status and managing the charging and discharging phases
- a microcontroller-based control section for managing system states and interfaces with the IPC
- a high-level, Windows-based, user-configurable software section for diagnosing the system and battery pack status and managing shutdowns

The architecture is common to all systems and is

customised by configuring specific parameters according to the type of use and consumption to optimise battery life

SOFTWARE

The UPS system operation is managed by high-level software, developed for Windows, divided into two parts:

- a service for monitoring the supply voltage and battery status and managing potential shutdowns
- a graphic application for configuring the behaviour in the event of a primary power failure and checking diagnostics

Furthermore, a regular system shutdown is commanded irrespective of the set parameters if a voltage below the minimum is measured to protect the battery from abnormal decay and avoid unexpected shutdowns

INTERVALLO DI SPEGNIMENTO CONFIGURABILE DA 10 SECONDI A 10 MINUTI

INDICAZIONE DELL'AUTONOMIA RESIDUA
CALCOLATA SUL CONSUMO REALE DEL SISTEMA

DIAGNOSTICA IN TEMPO REALE DELLO STATO DELLA BATTERIA

FUNZIONI DI LOG CON STORICIZZAZIONE DEI DATI

INTEGRAZIONE CON L'APPLICAZIONE DELL'UTENTE

BATTERY PACK TYPES

1) LEAD-ACID BATTERY

Lead-acid cell battery packs, compared to more modern technologies, are larger and bulker but they can supply high peak currents and operate over a wide temperature range (well above the 0-50°C guaranteed for systems). They consist of six elements for a nominal voltage of 12 V and can deliver a maximum of 100 W for approximately 2 minutes. They also integrate a temperature sensor and a protection circuit that cuts off the connection if the current is too high or the voltage is too low.

2) NICKEL-METAL-HYDRIDE (NIMH) BATTERIES

Battery packs with Ni-MH cells are characterised by a smaller size compared to lead-acid batteries and lower self-discharge during storage. They consist of 10 elements for a nominal voltage of 12V and can output a maximum of 60W for about 10 minutes. They also integrate a temperature sensor, a protection circuit that cuts off the connection if the current is too high or the voltage too low, and a switch for disconnecting the battery during transport.

INSTALLATION OF BATTERY PACKS

ASEM offers several installation options to choose the best location, facilitating wiring and/or replacement operations.

SEPARATED FROM THE SYSTEM



DIRECT ON THE SYSTEM



SEPARATED FROM THE SYSTEM, UP TO A DISTANCE OF 3M



MASS STORAGE DEVICES

ASEM provides a wide choice of mass storage devices for expanding the various IPCs according to customer requirements. All mass storage devices are tried and tested to guarantee correct operation in all working environments.



SSD COMPARISON TABLE

	SSD 2,5" SATA III	SSD mSATA SATA III	SSD M.2 2242 Sata III	SSD M.2 2280 NVMe PCle x4
BM1XY FAMILY	X	Х	✓	X
xx2150	X	✓	X	X
xx2200	✓	✓	X	X
xx2250	X	X	✓	X
BM3300 & BM3500	✓	✓	X	X
xx3400 & xx3600	✓	✓	X	X
QT-HT-PB3500	✓	X	✓	✓
BM3800	✓	X	✓	✓
xx5400 & xx5600	✓	X	✓	✓
VK3500 SERIES	X	X	X	✓
PR4x48	✓	✓	X	X
PR4x49	✓	✓	X	X
PR4x50	√	X	X	✓
PR4x51	✓	X	X	✓

LIST OF MASS STORAGE DEVICES:

- CFAST: available in ET (Extended Temperature) version
- SSDs: available in SATA, NVMe PCle and ET (Extended Temperature) versions
- HDDs: available in 2.5", 3.5" SATA III and 24x7 versions



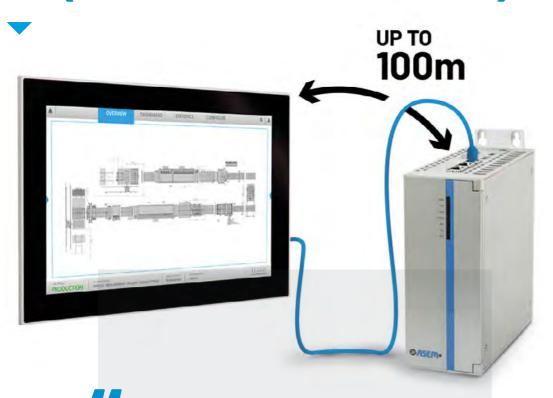




HDD COMPARISON TABLE

	HDD 2,5" SATA III	HDD 3,5" SATA III
BM1XY FAMILY	X	X
xx2150	X	X
xx2200	✓	X
xx2250	X	X
BM3300 & BM3500	✓	X
xx3400 & xx3600	✓	X
QT-HT-PB3500	✓	×
BM3800	✓	×
xx5400 & xx5600	✓	×
VK3500 SERIES	X	×
PR4x48	Х	✓
PR4x49	Х	✓
PR4x50	Х	✓
PR4x51	X	✓

RVL (REMOTE VIDEO LINK)



VIDEO REMOTE CONTROL SOLUTIONS

The ASEM Remote Video Link is an innovative technology for connecting industrial monitors up to 100 metres apart from the IPC using a single cable, through which DVI-D and USB 2.0 signals are sent using the HDBaseT standard.

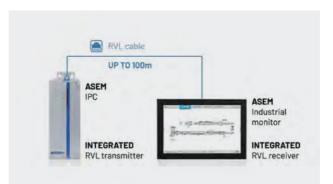
Signals are remoted up to 50 metres away using a Cat 5e SF/FTP cable or up to 100 metres away using a Cat 6A S/FTP cable.

The use of an industrial standard Ethernet cable and the RJ45 connector allows easy cabling in tight spaces and in presence of mobile systems (e.g. Arm Mounting systems).

ASEM can also supply an external RVL transmitter and/or receiver to remote video signals using third-party IPCs or monitors.

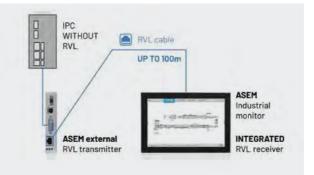
Both are powered at 24VDC. The ASEM RVL technology can create connections at long distances between any industrial device and in any specific application.

Here are the various cases of use:



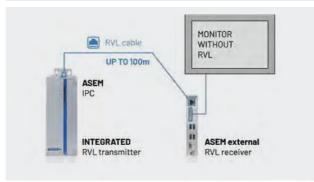
1) IPC AND ASEM INDUSTRIAL MONITORS

ASEM integrates RVL technology in its IPCs and industrial monitors. No additional external systems are required to connect the proprietary systems.



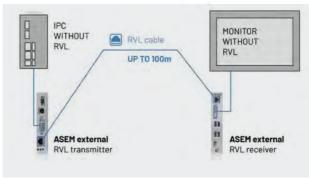
2) ASEM INDUSTRIAL MONITORS

ASEM provides external RVL transmitters for easily connecting a third-party IPC (or ASEM IPC not equipped with an integrated RVL transmitter) to the integrated RVL technology of a proprietary monitor.



3) ASEM IPC

ASEM provides external RVL receivers for easily connecting a third-party industrial monitor to the integrated RVL technology of a proprietary IPC.



4) IPC AND INDUSTRIAL MONITORS NOT EQUIPPED WITH INTEGRATED RVL

ASEM provides external RVL receivers and transmitters for easily connecting an industrial monitor to IPCs not equipped with integrated RVL transmitters.



TPMTRUSTED PLATFORM MODULE

What is TPM? It is a technology designed to offer hardware and software security features. The Trusted Computing Group (TCG) is the organisation that publishes and maintains the TPM specifications according to the international standard 11889 ISO/ IEC.

The TPM is useful for generating, storing and restricting the use of cryptographic keys, passwords and certificates. The dTPM (Discrete Trusted Platform Module) is a dedicated microcontroller designed to protect the hardware. It integrates cryptographic keys into devices and is used for secure cryptographic processes and secure storage of critical data.

ASEM PRODUCTS TPM

	iTPM	dTPM
BM1XY FAMILY	√	X
xx2150	X	X
xx2200	X	✓
xx2250	√	✓
BM3300	✓	✓
xx3400	✓	✓
QT-HT-PB3500	✓	✓
xx3600	✓	X
BM3800	✓	X
xx5400	✓	✓
xx5600	✓	✓
VK3500 SERIES	✓	X

Integrated TPM has been recently introduced on x86-based machines. In this form, the TPM is integrated into a chipset component of the existing platform. For instance, the integrated x86-based TPM function is a security and management engine module and is logically isolated from the other engine modules.

- The TPM is an endpoint security technology (*)
- IEC 62443-4-2 cites TPM as the gold standard for meeting the requirements of SL3 and SL4
- It checks that the operating system and firmware of the device are not tampered with
- It stores digital credentials in a secure hardware-based repository
- It sets passwords and manages keys
- It expands the number of smart cards, fingerprint readers and remote controls for multi-factor authentication
- It encrypts files and folders to control access
- It establishes status information to enable endpoint integrity
- It enables more secure wireless, remote, and VPN access
- For Windows® 11, TPM 2.0 is a requirement (PC must have TPM enabled)

(*) Industrial Internet Security Framework (https://www.iiconsortium.org/IISF.htm)

CONNECTIVITY •))

ASEM offers products with technologies that support the latest data communication interfaces and Internet connections.

Wi-Fi and Bluetooth, Cellular modules are available that can also be installed in combination with each other to provide multiple modes of use according to the specific needs of each automation environment, according to the requirements of Industry 4.0.

The technologies adopted offer intrinsic reliability, connection robustness and speed, which, using the recent 5G band present on the latest and future products, is combined with the guarantee of low latency and high capacity for data processing and simultaneous connections.

The MIMO and Diversity functions achieved through the dual antenna mounted directly on the product or remotely can be exploited to optimise connection stability and performance.

WIRELESS E BLUETOOTH CONNECTION TABLE

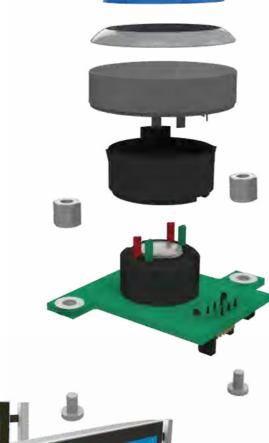
	Wi-Fi connection	Cellular connection
BM122	✓	✓
BM130	✓	✓
BM131	✓	✓
xx2150	✓	✓
QT-HT-PB2200	✓	✓
QT-HT-PB3400/3600	✓	✓
QT-HT-PB3500	✓	✓
QT-HT-PB5400/5600	✓	✓
VK3500 SERIES	✓	X

CONFIGURABLE CONTROL AREA

VK3500/MK200 SERIES



- Maximum configuration flexibility to customer specifications
- Frontally accessible for later configuration changes and/or additions
- Hard-wired connection modes
- The number of elements that can be installed depends on the size of the display: up to 13 elements on the landscape version and up to 8 elements on the portrait version with a 24" LCD (of which a maximum of 8 with hard-wired connection)
- The SIL3 emergency button has a separate hard-wired connection
- The elements are wired to two rear-access terminal blocks





Ø22 IP65 ELEMENTS







INDICATOR LIGHTS

 available in 5 colours (red, yellow, green, blue, white)

BUTTONS

- opaque version in 2 colours (grey and black)
- translucent version in 5 colours (red, yellow, green, blue, white)
- also with a customisable insert

EMERGENCY STOP BUTTON SIL3

 rotary or pull release, with or without LED indicator





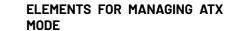


SELECTORS

- with key
- light keyless
- 1(90°) or 2 (±40°, ±60°) positions (toggle or stable actuation)

ADDITIONAL INTERFACES

- Gigabit Ethernet (RJ45)
- Transponder RFID reader/writer LF (125 kHz) and HF (13,56 MHz)
- USB 2.0 (Type-A)
- knob with incremental encoder
- buzzer



- opaque version
- translucent version
- with key



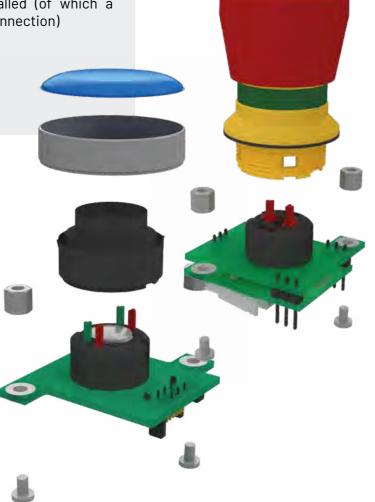
FRONTALLY ACCESSIBLE FOR LATER CONFIGURATION CHANGES AND/OR ADDITIONS

CONFIGURABLE CONTROL AREA

MX200



- Maximum configuration flexibility to customer specifications
- Frontally accessible for later configuration changes and/or additions
- Hard-wired connection modes
- Customer-selected elements can be Ø22 washable silicone or Ø30 low-profile stainless steel
- Up to 9 elements can be installed (of which a maximum of 8 with hard-wired connection)



Ø22 SILICONE ELEMENTS







INDICATOR LIGHTS

 available in 5 colours (red, yellow,
 translucent version in 5 colours green, blue, white)

BUTTONS

- (red, yellow, green, blue, white)
- grey opaque version

SELECTORS

- with key
- light keyless
- 1(90°) or 2 (±40°, ±60°) positions (toggle or stable actuation)



EMERGENCY STOP BUTTON

· rotary or pull release, with or without LED indicator

Ø30 STAINLESS STEEL, LOW-PROFILE ELEMENTS







INDICATOR LIGHTS

 available in 5 colours (red, yellow,
 translucent version in 5 colours
 with key green, blue, white)

BUTTONS

- (red, yellow, green, blue, white)
- grey opaque version
- with ring lighting

SELECTORS

- light keyless
- 1(90°) or 2 (±40°, ±60°) positions (toggle or stable actuation)

MECHANICAL ACCESSORIES

VK3500/MK200 SERIES

SIDE HANDLES





A set of two anodised aluminium side handles is available to facilitate system positioning

PERIMETER HANDLE





An anodised aluminium perimeter handle is available for easy positioning of the system and to protect the operator from accidental impacts

KEYBOARD HOLDER KIT





An aluminium keyboard holder kit painted RAL 9006 is available for the permanent installation of a keyboard and/ or mouse of the customer's choice

TYPES OF ASSEMBLY



ARM/VESA Mounting IPC & Monitor

VK3500/MK200 SERIES

VESA MOUNTING

The VK3500 and MK200 systems are available with chassis having an attachment compatible with VESA 75/100 standards



ARM ASSEMBLY

VK3500 and MK200 systems are available with arm-mounted chassis compatible with RITTAL CP40/ROLEC TARAPLUS/ HASEKE ULT KUPPLUNG 48



MX200 SERIES

The MX200 systems have a chassis with a specific attachment with six M5-type screws arranged with a 100mm centre distance. ASEM provides its customers with all the technical specifications for creating their own attachment flange. An arm-mounting flange for Ø48mm tubes is optionally supplied.



SERVICES AND SUPPORT







CUSTOMER-ORIENTED PHILOSOPHY

The ASEM customer-oriented philosophy means constant attention and care for the customer's needs and a comprehensive and qualified preand after-sales service. All company processes are designed and organised to ensure maximum customer satisfaction with excellent product quality and operational flexibility to respond promptly to changing market demands. ASEM ensures the quality of products and processes by systematically and rigorously applying its quality system according to UNI EN ISO 9001:2015. The quality system, introduced in 1999, is certified by Intertek and is constantly updated to improve the business operation effectiveness and efficiency.



ASSISTANCE AND REPAIRS

ASEM offers its customers excellent assistance and consulting services for hardware and software, in addition to a timely repair service for products and systems.

ASEM guarantees service through a team of specialised technicians to optimise service activities and minimise response times in the following ways:

PHONE HELP DESK SERVICE

- For hardware and systems, dial +39 0432 967250, from Mondays to Fridays from 9 a.m. to 12:30 noon and from 2 to 5:30 p.m.
- For software, dial +39 0362 859124, from Mondays to Fridays from 9 a.m. to 12:30 noon and from 2 to 5:30 p.m.

ONLINE HELP DESK SERVICE

Available for hardware and software, it allows access to the ASEM customer care directly online on the company website at:

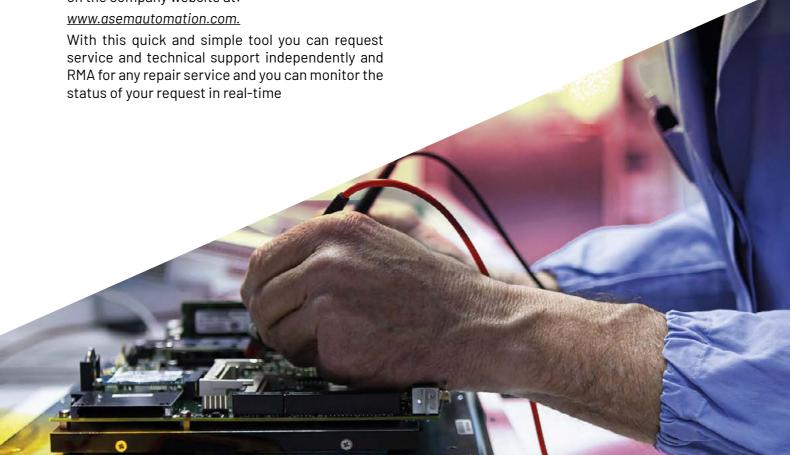
E-MAIL SERVICE

Please send requests for hardware and software support to the following e-mail addresses:

- For hardware and systems: suptec@asem.it;
- For software: supportsw@asem.it

For software support, the "Asem Remote Support Tool" is also available at:

http://get.teamviewer.com/asemsup



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